

Five/Ten Output Clock Generator/Buffer

FEATURES

- Universal Input Buffers That Accept LVPECL, LVDS, or LVC MOS Level Signaling
- Fully Configurable Outputs Including Frequency, Output Format, and Output Skew
- Output Multiplexer That Serves as a Clock Switch Between the Three Reference Inputs and the Outputs
- Clock Generation Via AT-Cut Crystal
- Integrated EEPROM Determines Device Configuration at Power-up
- Low Additive Jitter Performance
- Universal Output Blocks Support up to 5 Differential, 10 Single-ended, or Combinations of Differential or Single-ended:
 - Low Additive Jitter
 - Output Frequency up to 1.5 GHz
 - LVPECL, LVDS, LVC MOS, and Special High Output Swing Modes
 - Independent Output Dividers Support Divide Ratios from 1–80
 - Independent limited Coarse Skew Control on all Outputs
- Flexible Inputs:
 - Two Universal Differential Inputs Accept Frequencies up to 1500 MHz (LVPECL), 800 MHz (LVDS), or 250 MHz (LVC MOS).
 - One Auxiliary Input Accepts Single Ended Clock Source or Crystal. Auxiliary Input Accepts Crystals in the Range of 2 MHz–42 MHz or an LVC MOS Input up to 75 MHz.
 - Clock Generator Mode Using Crystal Input.
- Typical Power Consumption 1.0W at 3.3V (see Table 27)
- Integrated EEPROM Stores Default Settings; Therefore, The Device Powers up in a Known, Predefined State.
- Offered in QFN-48 Package
- ESD Protection Exceeds 2kV HBM
- Industrial Temperature Range –40°C to 85°C

APPLICATIONS

- Data Converter and Data Aggregation Clocking
- Wireless Infrastructure
- Switches and Routers
- Medical Electronics
- Military and Aerospace
- Industrial
- Clock Fan-out

DESCRIPTION

The CDCE18005 is a high performance clock generator and distributor featuring a high degree of configurability via a SPI interface, and programmable start up modes determined by on-board EEPROM. Specifically tailored for buffering clocks for data converters and high-speed digital signals, the CDCE18005 achieves low additive jitter in the 50 fs RMS⁽¹⁾ range. The clock distribution block includes five individually programmable outputs that can be configured to provide different combinations of output formats (LVPECL, LVDS, LVC MOS). Each output can also be programmed to a unique output frequency (up to 1.5 GHz⁽²⁾) and skew relationship via a programmable delay block. If all outputs are configured in single-ended mode (e.g. LVC MOS), the CDCE18005 supports up to ten outputs. Each output can select one of three clock input sources. The input block includes two universal differential inputs which support frequencies up to 1500 MHz and an auxiliary single ended input that can be connected to a CMOS level clock or configured to connect to an external crystal via an on board oscillator block.

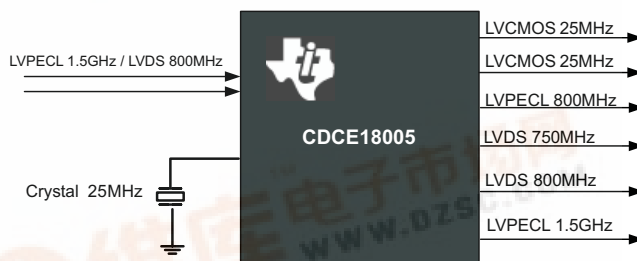


Figure 1. CDCE18005 Application Example

- (1) 12 kHz to 20 MHz integration bandwidth.
- (2) Maximum output frequency depends on the output format selected



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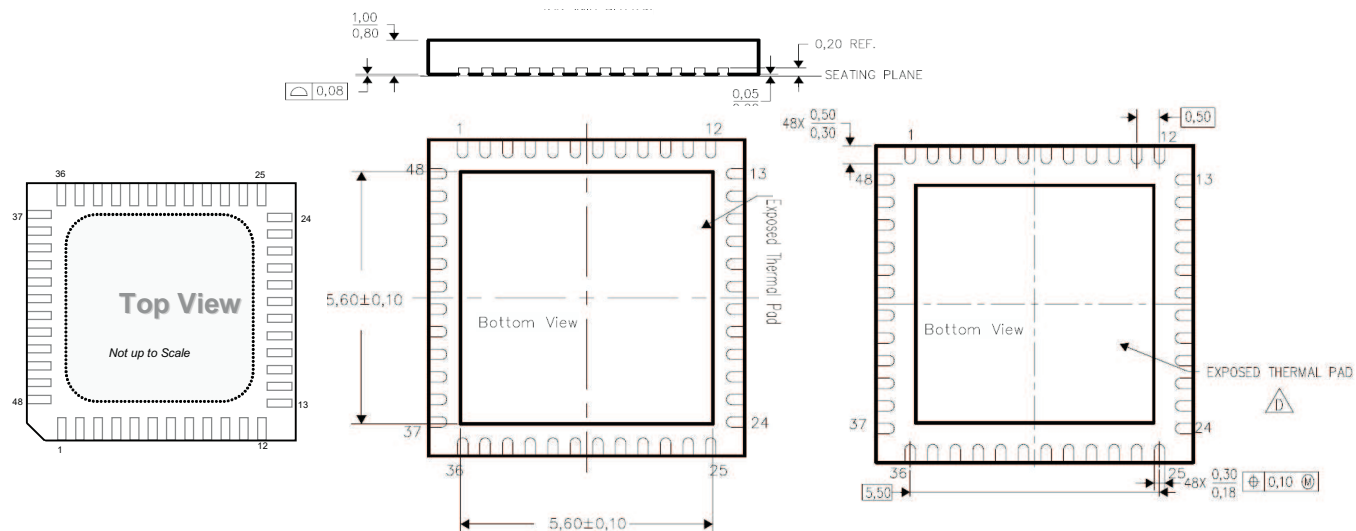
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DEVICE INFORMATION

PACKAGE

The CDCE18005 is packaged in a 48-Pin Plastic Quad Flatpack Package with enhanced bottom thermal pad for heat dissipation. The Texas Instruments Package Designator is: **RGZ (S-PQFP-N48)**



PIN FUNCTIONS

PIN		TYPE	DESCRIPTION
NAME	QFN		
VCC_OUT	8, 11, 15, 18, 21, 26, 29, 32	Power	3.3V Supply for the Output Buffers
VCC_CORE	5, 39, 42, 34, 35	Power	3.3V Core Voltage Circuitry
VCC_IN_PRI	47	A. Power	3.3V References Input Buffer and Circuitry Supply Voltage.
VCC_IN_SEC	1	A. Power	3.3V References Input Buffer and Circuitry Supply Voltage.
VCC_IN_AUX	44	A. Power	3.3V Crystal Oscillator Input Circuitry.
GND	36	Ground	Ground (All internal Ground Pins are connected to the PAD)
GND	PAD	Ground	Ground is on Thermal PAD. See Layout recommendation
SPI_MISO	22	OD	In SPI Mode it is an Open Drain Output and it functions as a Master In Slave Out as a serial Control Data Output to CDCE18005 .
SPI_LE	25	I	LVC MOS input, control Latch Enable for Serial Programmable Interface (SPI), with Hysteresis in SPI Mode. The input has an internal 150-k Ω pull-up resistor if left unconnected it will default to logic level "1".
SPI_CLK	24	I	LVC MOS input, serial Control Clock Input for the SPI bus interface, with Hysteresis. The input has an internal 150-k Ω pull-up resistor if left unconnected it will default to logic level "1".
SPI_MOSI	23	I	LVC MOS input, Master Out Slave In as a serial Control Data Input to CDCE18005 for the SPI bus interface. The input has an internal 150-k Ω pull-up resistor if left unconnected it will default to logic level "1".
TEST_MODE	33	I	Pull High or leave unconnected
TEST_MODE2	31	I	Pull High or leave unconnected
Power_Down	12	I	Active Low. Power down mode can be activated via this pin. See Table 13 for more details. The input has an internal 150-k Ω pull-up resistor if left unconnected it will default to logic level "1". SPI_LE has to be HIGH in order for the rising edge of Power_Down signal to load the EEPROM.
SYNC	14	I	Active Low. Sync mode can be activated via this pin. See Table 13 for more details. The input has an internal 150-k Ω , pull-up resistor if left unconnected it will default to logic level "1".
AUX IN	43	I	Auxiliary Input is a single ended input including an on-board oscillator circuit so that a crystal may be connected.
AUX OUT	13	O	Auxiliary Output LVC MOS level that can be programmed via SPI interface to be driven by Output 2 or Output 3.
PRI REF+	45	I	Universal Input Buffer (LVPECL, LVDS, LVC MOS) positive input for the Primary Reference Clock,
PRI REF–	46	I	Universal Input Buffer (LVPECL, LVDS) negative input for the Primary Reference Clock. In case of LVC MOS signaling Ground this pin.
SEC REF+	3	I	Universal Input Buffer (LVPECL, LVDS, LVC MOS) positive input for the Secondary Reference Clock,
SEC REF–	2	I	Universal Input Buffer (LVPECL, LVDS,) negative input for the Secondary Reference Clock. In case of LVC MOS signaling Ground this pin.
TESTOUTA	30	Analog	Analog Test Point for Use for TI Internal Testing. Pull Down to GND Via a 1k Ω Resistor.
NC	4		This Pin is not used
NC	38		This Pin is not used
VBB	48	Analog	Capacitor for the internal termination Voltage. Connect to a 1 μ F Capacitor (Y5V)
NC	40		This Pin is not used
NC	41		This Pin is not used
NC	37		This Pin is not used
U0P:U0N U1P:U1N U2P:U2N U3P:U3N U4P:U4N	27, 28 19, 20 16, 17 9, 10 6, 7	O	The Main outputs of CDCE18005 are user definable and can be any combination of up to 5 LVPECL outputs, 5 LVDS outputs or up to 10 LVC MOS outputs. The outputs are selectable via SPI interface. The power-up setting is EEPROM configurable.

FUNCTIONAL DESCRIPTION

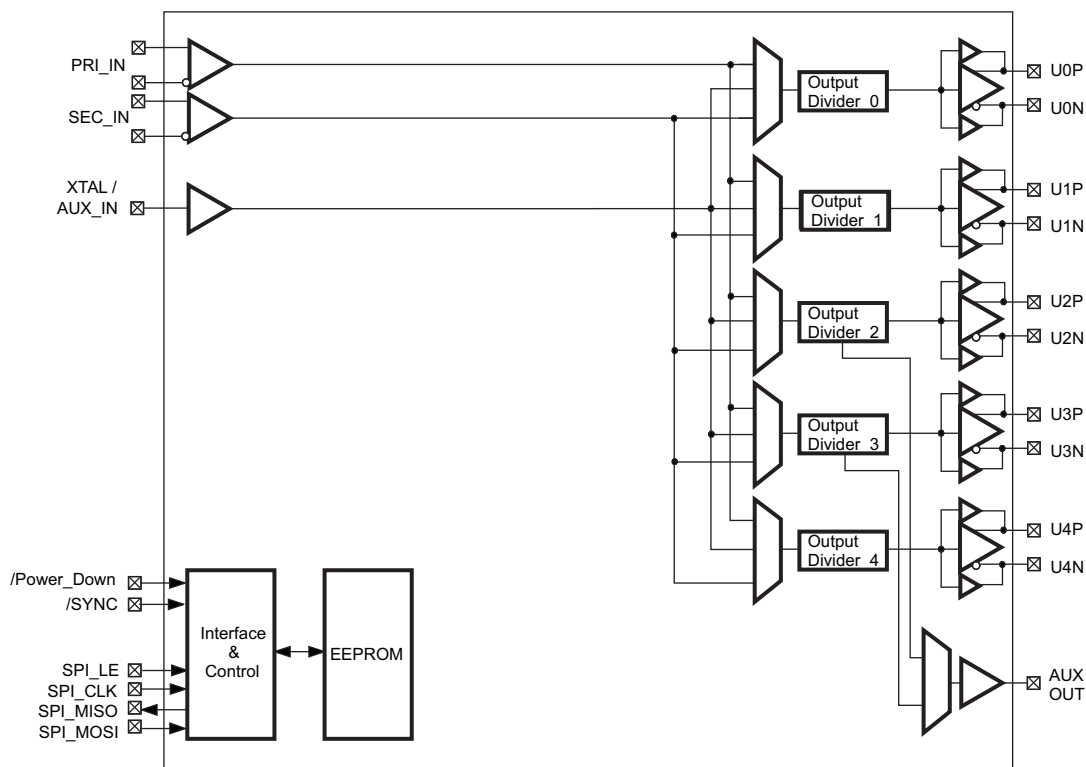


Figure 3. CDCE18005 Block Diagram

The CDCE18005 comprises three primary blocks: the interface and control block, the input block and the output block. In order to determine which settings are appropriate for any specific combination of input/output frequencies, a basic understanding of these blocks is required. The interface and control block determines the state of the CDCE18005 at power-up based on the contents of the

on-board EEPROM. In addition to the EEPROM, the SPI port is available to configure the CDCE18005 by writing directly to the device registers after power-up. The input block buffers three clock signals, converts them to differential signals, and drives them onto an internal clock distribution bus. The output block provides five separate clock channels that are fully programmable and configurable to select and condition one of four internal clock sources

NOTE:

This Section of the data sheet provides a high-level description of the features of the CDCE18005 for purpose of understanding its capabilities. For a complete description of device registers and I/O, please refer to the Device Configuration Section.

Interface and Control Block

The CDCE18005 is a highly flexible and configurable architecture and as such contains a number of registers so that the user may specify device operation. The contents of nine 28-bit wide registers implemented in static RAM determine device configuration at all times. The CDCE18005 implements the SPI Interface Mode. SPI Interface Mode is used to access the device RAM and EEPROM either during normal operation (if the host system provides a native SPI interface) or during device configuration (i.e. device programming). During power up the EEPROM content gets copied into the registers after the detection of a valid device power-up. The EEPROM can be locked enabling the designer to implement a fault tolerant design.

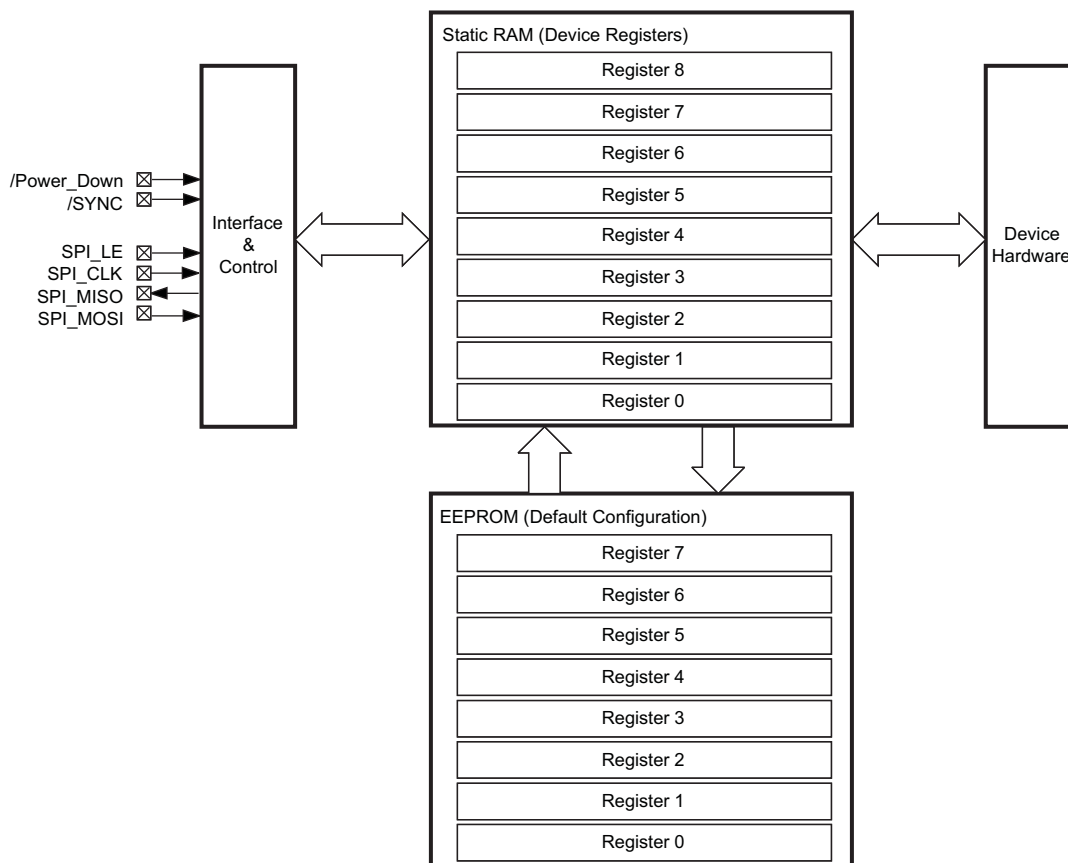


Figure 4. CDCE18005 Interface and Control Block

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Input Block

The Input Block includes a pair of Universal Input Buffers and an Auxiliary Input. The Input Block buffers the incoming signals and facilitates signal routing to the Internal Clock Distribution bus. The Internal Clock Distribution Bus connects to all output blocks discussed in the next section. Therefore, a clock signal present on the Internal Clock Distribution bus can appear on any or all of the device outputs.

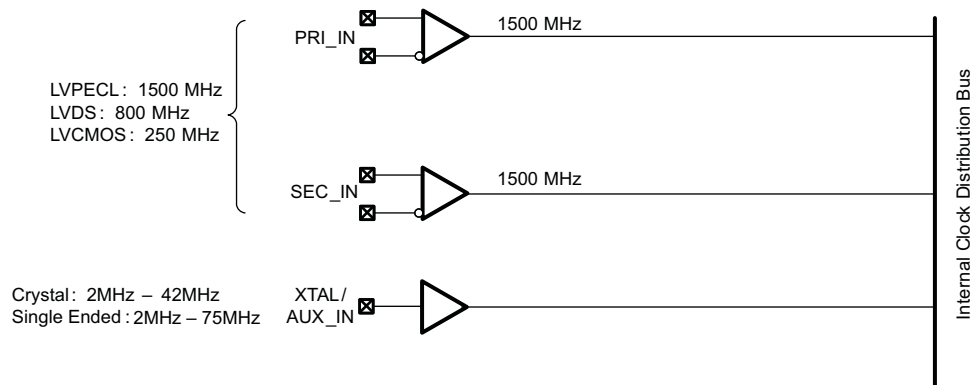


Figure 5. CDCE18005 Input Block

Output Block

Each of the five identical output blocks incorporates an output multiplexer, a clock divider module, and a universal output array as shown.

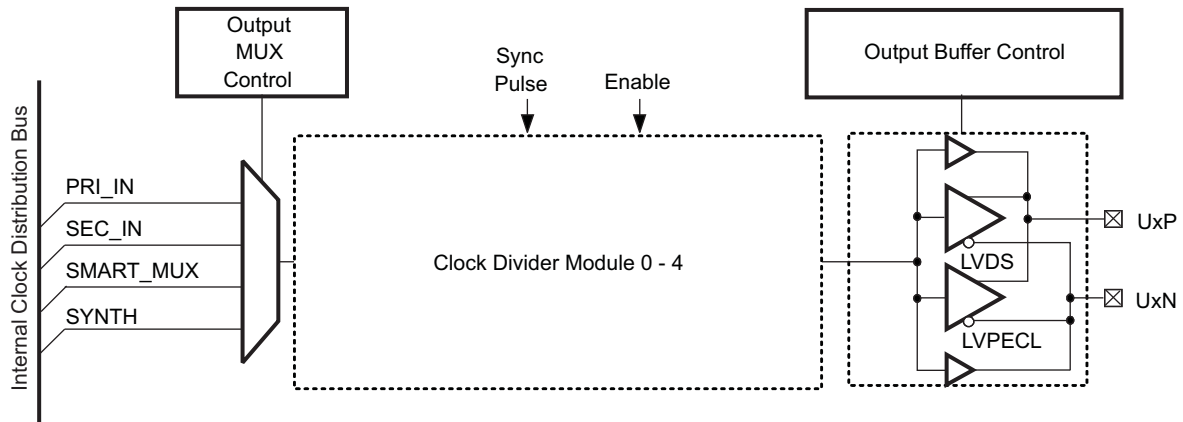


Figure 6. CDCE18005 Output Block (1 of 5)

Clock Divider Module 0–4

The following shows a simplified version of a Clock Divider Module (CDM). If an individual clock output channel is not used, then the user should disable the CDM and Output Buffer for the unused channel to save device power. Each channel includes two 7-bit registers to control the divide ratio used and the clock phase for each output.

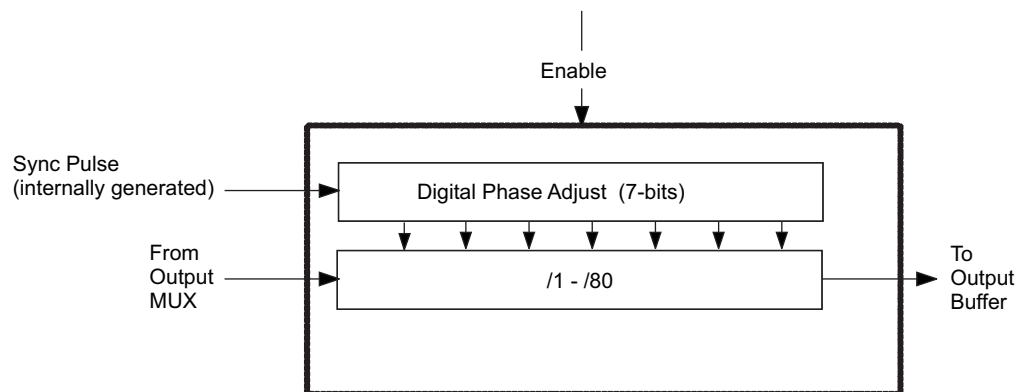


Figure 7. CDCE18005 Output Divider Module (1 of 5)

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ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		VALUE	UNIT
V _{CC}	Supply voltage range ⁽²⁾	−0.5 to 4.6	V
V _I	Input voltage range ⁽³⁾	−0.5 to V _{CC} + 0.5	V
V _O	Output voltage range ⁽³⁾	−0.5 to V _{CC} + 0.5	V
	Input Current (V _I < 0, V _I > V _{CC})	±20	mA
	Output current for LVPECL/LVCMOS Outputs (0 < V _O < V _{CC})	±50	mA
T _J	Maximum junction temperature	125	°C
T _{stg}	Storage temperature range	−65 to 150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated *under recommended operating conditions* is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.
- (2) All supply voltages have to be supplied simultaneously.
- (3) The input and output negative voltage ratings may be exceeded if the input and output clamp–current ratings are observed.

THERMAL CHARACTERISTICS

Package Thermal Resistance for QFN (RGZ) Package ⁽¹⁾ ⁽²⁾

AIRFLOW (LFM)		θ _{JP} (°C/W) ⁽³⁾	θ _{JA} (°C/W)
0	JEDEC Compliant Board (6X6 VIAs on PAD)	2	28.9
100	JEDEC Compliant Board (6X6 VIAs on PAD)	2	20.4
0	Recommended Layout (7X7 VIAs on PAD)	2	27.3
100	Recommended Layout (7X7 VIAs on PAD)	2	20.3

- (1) The package thermal impedance is calculated in accordance with JESD 51 and JEDEC2S2P (high-k board).
- (2) Connected to GND with 36 thermal vias (0,3 mm diameter).
- (3) θ_{JP} (Junction – Pad) is used for the QFN Package, because the main heat flow is from the Junction to the GND-Pad of the QFN.

ELECTRICAL CHARACTERISTICS OPERATING CONDITIONS

recommended operating conditions for the **CDCE18005** device for under the specified Industrial temperature range of –40°C to 85°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY						
V _{CC}	Supply voltage		3	3.3	3.6	V
V _{CC_IN} & V _{Core}	Analog supply voltage		3	3.3	3.6	
P _{LVPECL}	REF at 491.52 MHz, Outputs are LVPECL	Output 1 = 491.52 MHz (LVCMOS = 245 MHz) Output 2 = 245.76 MHz Output 3 = 122.88 MHz Output 4 = 61.44 MHz Output 5 = 30.72 MHz	1.6			W
P _{LVDS}	REF at 491.52 MHz, Outputs are LVDS		1.3			W
P _{LVCMOS}	REF at 491.52 MHz, Outputs are LVCMOS		1.5			W
P _{OFF}	REF at 491.52 MHz	Dividers are disabled. Outputs are disabled.	0.45			W
P _{PD}		Device is powered down	20			mW
DIFFERENTIAL INPUT MODE (PRI_IN, SEC_IN)						
V _{INPP}	Input amplitude (V _{IN} – V _{IN})		0.1		1.3	V
V _{IC}	Common-mode input voltage		1.0		V _{CC} –0.3	V
I _{IH}	Differential input current high (no internal termination)	V _I = V _{CC} , V _{CC} = 3.6 V			20	μA
I _{IL}	Differential input current low (no internal termination)	V _I = 0 V, V _{CC} = 3.6 V	–20		20	μA
	Input Capacitance on PRI_IN, SEC_IN			3		pF
LVCMOS INPUT MODE (AUX_IN)						
V _{IL}	Low-level input voltage LVCMOS		0		0.3 V _{CC}	V
V _{IH}	High-level input voltage LVCMOS		0.7 V _{CC}		V _{CC}	V
	V _{IK} LVCMOS input clamp voltage	V _{CC} = 3 V, I _I = –18 mA			–1.2	V
I _{IH}	LVCMOS input current	V _I = V _{CC} , V _{CC} = 3.6 V		300		μA
I _{IL}	LVCMOS input	V _I = 0 V, V _{CC} = 3.6 V	–10		10	μA
C _I	Input capacitance (LVCMOS signals)	V _I = 0 V or V _{CC}		8		pF
CRYSTAL INPUT SPECIFICATIONS						
	Crystal shunt capacitance				20	pF
	Equivalent series resistance (ESR)				50	Ω
LVCMOS INPUT MODE (SPI_CLK,SPI_MOSI,SPI_LE,PD,SYNC,REF_SEL, PRI_IN, SEC_IN)						
	Low-level input voltage LVCMOS,		0		0.3 V _{CC}	V
	High-level input voltage LVCMOS		0.7 V _{CC}		V _{CC}	V
V _{IK}	LVCMOS input clamp voltage	V _{CC} = 3 V, I _I = –18 mA			–1.2	V
I _{IH}	LVCMOS input current	V _I = V _{CC} , V _{CC} = 3.6 V				μA
I _{IL}	LVCMOS input (Except PRI_IN and SEC_IN)	V _I = 0 V, V _{CC} = 3.6 V	–10		–40	μA
I _{IL}	LVCMOS input (PRI_IN and SEC_IN)	V _I = 0 V, V _{CC} = 3.6 V	–10		10	μA
C _I	Input capacitance (LVCMOS signals)	V _I = 0 V or V _{CC}		3		pF

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ELECTRICAL CHARACTERISTICS OPERATING CONDITIONS (Continued)

recommended operating conditions for the **CDCE18005** device for under the specified Industrial temperature range of -40°C to 85°C

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
SPI OUTPUT (MISO)							
I _{OH}	High-level output current	V _{CC} = 3.3 V,	V _O = 1.65 V		−30		mA
I _{OL}	Low-level output current	V _{CC} = 3.3 V,	V _O = 1.65 V		33		mA
V _{OH}	High-level output voltage for LVCMOS outputs	V _{CC} = 3 V,	I _{OH} = −100 μA	V _{CC} −0.5			V
V _{OL}	Low-level output voltage for LVCMOS outputs	V _{CC} = 3 V,	I _{OL} = 100 μA			0.3	V
C _O	Output capacitance on MISO	VCC = 3.3 V; VO = 0 V or VCC			3		pF
I _{OZH}	3-state output current	V _O = V _{CC} , V _O = 0 V			5		μA
I _{OZL}					−5		
VBB							
VBB	Termination voltage for reference inputs.	I _{BB} = −0.2 mA, Depending on the setting.		0.9		1.9	V
INPUT BUFFERS INTERNAL TERMINATION RESISTORS (PRI_IN and SEC_IN)							
Termination resistance		Single ended			50		Ω

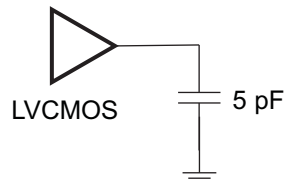
(1) All typical values are at $V_{CC} = 3.3\text{ V}$, temperature = 25°C

ELECTRICAL CHARACTERISTICS OPERATING CONDITIONS (Continued)

recommended operating conditions for the **CDCE18005** device for under the specified Industrial temperature range of –40°C to 85°C

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
LVC MOS OUTPUT OR AUXILIARY OUTPUT							
f _{clk}	Output frequency, see Figure Below	Load = 5 pF to GND				250	MHz
V _{OH}	High-level output voltage for LVC MOS outputs	V _{CC} = min to max	I _{OH} = −100 μA	V _{CC} −0.5			
V _{OL}	Low-level output voltage for LVC MOS outputs	V _{CC} = min to max	I _{OL} =100 A	0.3			V
I _{OH}	High-level output current	V _{CC} = 3.3 V	V _O = 1.65 V	−30			mA
I _{OL}	Low-level output current	V _{CC} = 3.3 V	V _O = 1.65 V	33			mA
t _{pd(LH)/} t _{pd(HL)}	Propagation delay from PRI_IN or SEC_IN to Outputs (LVC MOS to LVC MOS)	V _{CC} /2 to V _{CC} /2		4			ns
t _{sk(o)}	Skew, output to output For Y0 to Y4	All Outputs set at 200 MHz, Reference = 200 MHz		75			ps
C _O	Output capacitance on Y0 to Y4	V _{CC} = 3.3 V; V _O = 0 V or V _{CC}		5			pF
I _{OZH}	3-State LVC MOS output current	V _O = V _{CC}		5			μA
I _{OZL}		V _O = 0 V		−5			μA
I _{OPDH}	Power Down output current	V _O = V _{CC}		25			μA
I _{OPDL}		V _O = 0 V		5			μA
Duty cycle LVC MOS		50% to 50%		45%		55%	
t _{slew-rate}	Output rise/fall slew rate			3.6	5.2		V/ns

(1) All typical values are at $V_{CC} = 3.3 V$, temperature = 25°C



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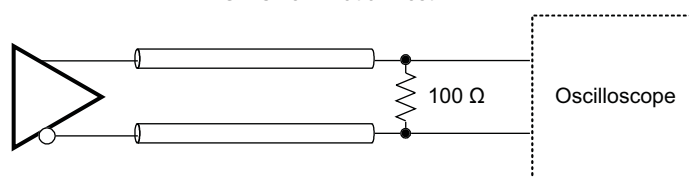
ELECTRICAL CHARACTERISTICS OPERATING CONDITIONS (Continued)⁽¹⁾⁽²⁾⁽³⁾⁽⁴⁾

recommended operating conditions for the **CDCE18005** device for under the specified Industrial temperature range of –40°C to 85°C

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽⁵⁾	MAX	UNIT
LVDS OUTPUT						
f_{clk}	Output frequency	Configuration Load (100 Ω)	0		800	MHz
$ V_{\text{OD}} $	Differential output voltage	$R_L = 100 \Omega$	270		550	mV
ΔV_{OD}	LVDS VOD magnitude change				50	mV
V_{OS}	Offset Voltage	–40°C to 85°C		1.24		V
ΔV_{OS}	VOS magnitude change			40		mV
	Short circuit Vout+ to ground	$V_{\text{OUT}} = 0$			27	mA
	Short circuit Vout– to ground	$V_{\text{OUT}} = 0$			27	mA
$t_{\text{pd(LH)}}/t_{\text{pd(HL)}}$	Propagation delay from PRI_IN or SEC_IN to outputs (LVDS to LVDS)	Crosspoint to Crosspoint		3.1		ns
$t_{\text{sk(o)}}^{(6)}$	Skew, output to output For Y0 to Y4	All Outputs set at 200 MHz Reference = 200 MHz		25		ps
C_{O}	Output capacitance on Y0 to Y4	$V_{\text{CC}} = 3.3 \text{ V}$; $V_{\text{O}} = 0 \text{ V}$ or V_{CC}		5		pF
I_{OPDH}	Power down output current	$V_{\text{O}} = V_{\text{CC}}$			25	μA
I_{OPDL}	Power down output current	$V_{\text{O}} = 0 \text{ V}$			5	μA
	Duty cycle	50% input	45%		55%	
t_r / t_f	Rise and fall time	20% to 80% of $V_{\text{OUT(PP)}}$	110	160	190	ps
LVCMOS-TO-LVDS						
$t_{\text{skP_c}}$	Output skew between LVCMOS and LVDS outputs ⁽⁷⁾	Crosspoint to VCC/2	0.9	1.4	1.9	ns

- (1) This is valid only for same REF_IN clock and Y output clock frequency
- (2) VINPP minimum and maximum is required to maintain ac specifications; the actual device function tolerates at a minimum VINPP of 100mV.
- (3) Lock output has a 80 k Ω pull-down resistor.
- (4) The phase of LVCMOS is lagging in reference to the phase of LVDS.
- (5) All typical values are at $V_{\text{CC}} = 3.3 \text{ V}$, temperature = 25°C
- (6) The $t_{\text{sk(o)}}$ specification is only valid for equal loading of all outputs.
- (7) Operating the LVCMOS or LVDS output above the maximum frequency will not cause a malfunction to the device, but the output signal swing might no longer meet the output specification

LVDS DC Termination Test



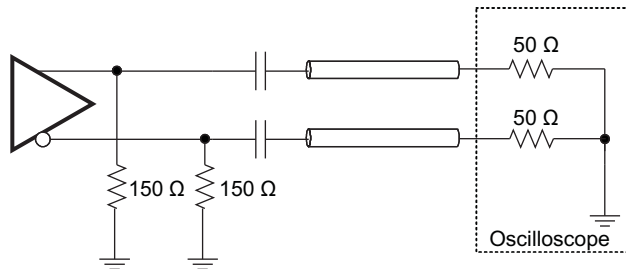
ELECTRICAL CHARACTERISTICS OPERATING CONDITIONS (Continued)

recommended operating conditions for the **CDCE18005** device for under the specified Industrial temperature range of -40°C to 85°C

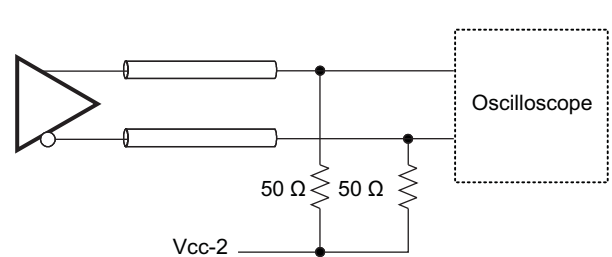
PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
LVPECL OUTPUT						
f _{clk}	Output frequency	Configuration load (Figures below)	0		1500	MHz
V _{OH}	LVPECL high-level output voltage load		V _{CC} −1.06		V _{CC} −0.88	V
V _{OL}	LVPECL low-level output voltage load		V _{CC} −2.02		V _{CC} −1.58	V
V _{OD}	Differential output voltage		610		970	mV
t _{pd(LH)/} t _{pd(HL)}	Propagation delay from PRI_IN or SEC_IN to outputs (LVPECL to LVPECL)	Crosspoint to Crosspoint		3.4		ns
t _{sk(o)}	Skew, output to output For Y0 to Y4	All Outputs set at 200 MHz Reference = 200MHz		25		ps
C _O	Output capacitance on Y0 to Y4	V _{CC} = 3.3 V; V _O = 0 V or V _{CC}		5		pF
I _{OPDH}	Power Down output current	V _O = V _{CC}			25	μA
I _{OPDL}		V _O = 0 V			5	μA
Duty Cycle		50% input	45%		55%	
t _r / t _f	Rise and fall time	20% to 80% of V _{outpp}	55	75	135	ps
LVDS-TO-LVPECL						
t _{skP_C}	Output skew between LVDS and LVPECL outputs	Crosspoint to Crosspoint	0.9	1.1	1.3	ns
LVC MOS-TO-LVPECL						
t _{skP_C}	Output skew between LVC MOS and LVPECL outputs	V _{CC} /2 to crosspoint	−150	260	700	ps
LVPECL HI-PERFORMANCE OUTPUT						
V _{OH}	LVPECL high-level output voltage load		V _{CC} −1.11		V _{CC} −0.87	V
V _{OL}	LVPECL low-level output voltage load		V _{CC} −2.06		V _{CC} −1.73	V
V _{OD}	Differential output voltage		760		1160	mV
t _r / t _f	Rise and fall time	20% to 80% of V _{outpp}	55	75	135	ps

(1) All typical values are at $V_{\text{CC}} = 3.3\text{ V}$, temperature = 25°C

LVPECL AC Termination Test



LVPECL DC Termination Test



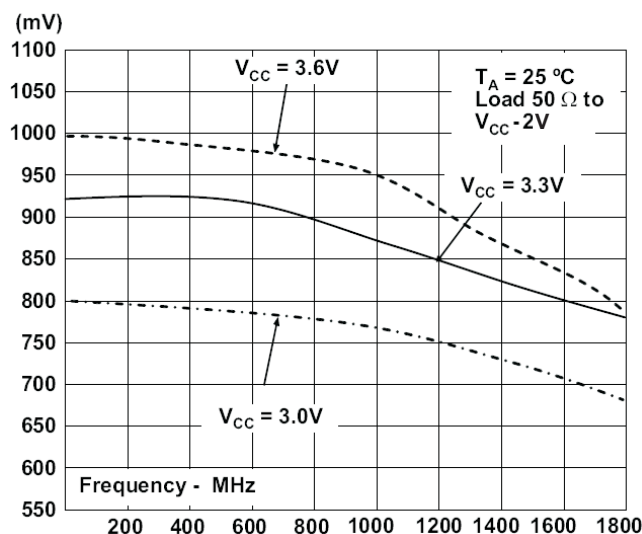
**LVPECL OUTPUT SWING
vs
FREQUENCY**


Figure 8.

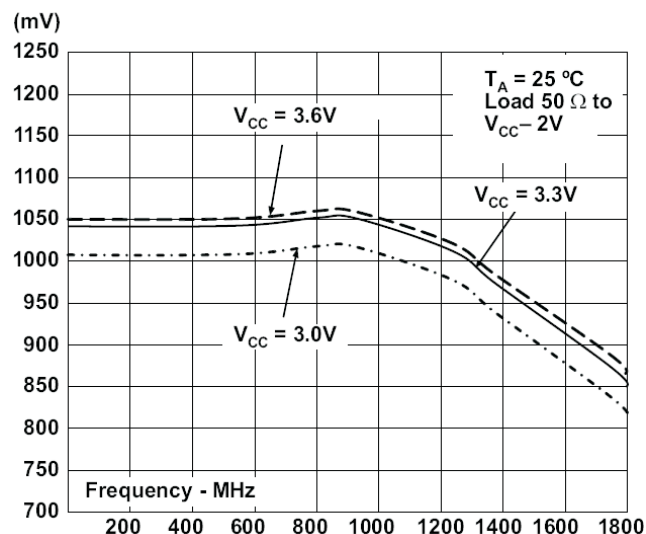
**HI SWING LVPECL OUTPUT SWING
vs
FREQUENCY**


Figure 9.

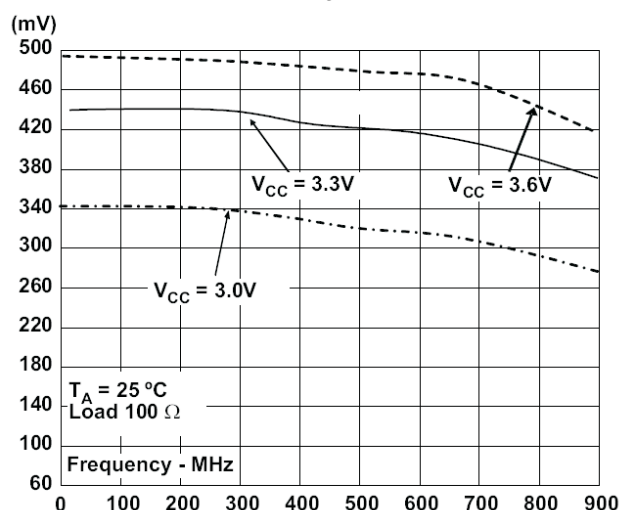
**LVDS OUTPUT SWING
vs
FREQUENCY**


Figure 10.

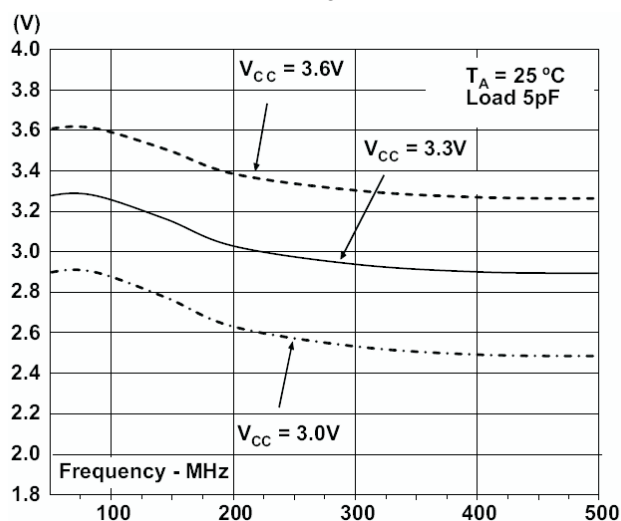
**LVC MOS OUTPUT SWING
vs
FREQUENCY**


Figure 11.

TIMING REQUIREMENTS

over recommended ranges of supply voltage, load and operating free air temperature (unless otherwise noted)

PARAMETER		MIN	TYP	MAX	UNIT
PRI_IN/SEC_IN_IN REQUIREMENTS					
f _{max}	For Single ended Inputs (LVCMOS) on PRI_IN and SEC_IN			250	MHz
	For Differential Inputs on PRI_IN & SEC_IN			1500	MHz
Single ended clock duty cycle of PRI_IN or SEC_IN at V _{CC} / 2		40%		60%	
Differential clock duty cycle of PRI_IN or SEC_IN at V _{CC} / 2		40%		60%	
AUXILARY_IN REQUIREMENTS					
f _{REF}	Single ended Inputs (LVCMOS) on AUX_IN	2		75	MHz
f _{REF}	Crystal single ended Inputs (AT-Cut Crystal Input)	2		42	MHz
Power_Down, SYNC, REF_SEL REQUIREMENTS					
t _r / t _f	Rise and fall time of the PD, SYNC, REF_SEL signal from 20% to 80% of V _{CC}			4	ns

PHASE NOISE ANALYSIS

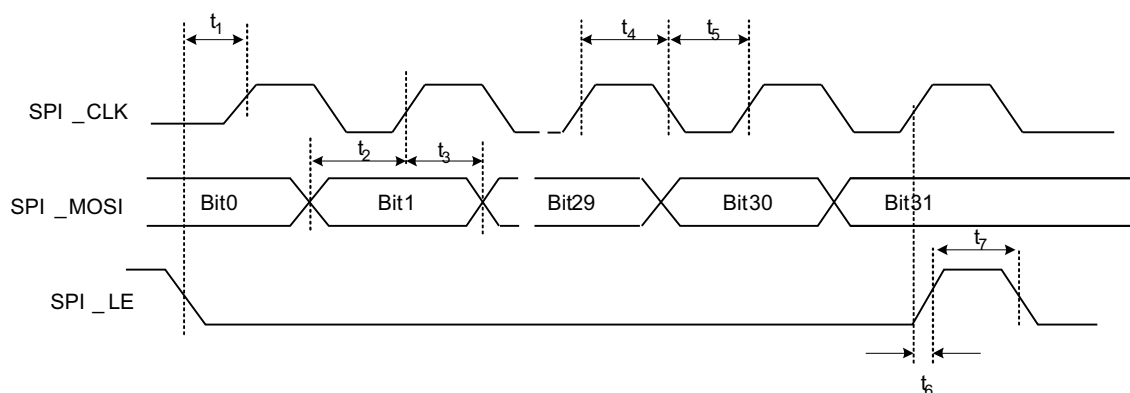
Table 1. Output Phase Noise for a 491.52 MHz External Reference

Phase Noise Specifications under following configuration: REF = 491.52 MHz Diff, LVPECL					
Phase Noise	Reference 491.52 MHz	LVPECL 491.52 MHz	LVDS 245.52 MHz	LVC MOS 122.88 MHz	Unit
10 Hz	-86	-84	-90	-96	dBc/Hz
100 Hz	-100	-100	-105	-111	dBc/Hz
1 kHz	-108	-109	-115	-121	dBc/Hz
10 kHz	-130	-130	-136	-140	dBc/Hz
100 kHz	-135	-135	-140	-145	dBc/Hz
1 MHz	-138	-142	-143	-148	dBc/Hz
10 MHz	-150	-148	-150	-153	dBc/Hz
20 MHz	-150	-148	-150	-152	dBc/Hz
Jitter(RMS) 10k~20Mhz	84	93	150	206	fs

Table 2. Output Phase Noise for a 25 MHz Crystal Reference

Phase Noise Specifications under following configuration: REF = 25 MHz, SE:LVC MOS					
Phase Noise	Reference 25.00 MHz	LVPECL 25 MHz	LVDS 25 MHz	LVC MOS 25 MHz	Unit
10 Hz	-	-83	-82	-82	dBc/Hz
100 Hz	-	-115	-116	-115	dBc/Hz
1 kHz	-	-142	-142	-141	dBc/Hz
10 kHz	-	-152	-149	-151	dBc/Hz
100 kHz	-	-155	-151	-155	dBc/Hz
1 MHz	-	-157	-151	-158	dBc/Hz
5 MHz	-	-157	-151	-158	dBc/Hz
Jitter(RMS) 10k~20 MHz	-	275	345	249	fs

SPI CONTROL INTERFACE TIMING


Figure 12. Timing Diagram for SPI Write Command

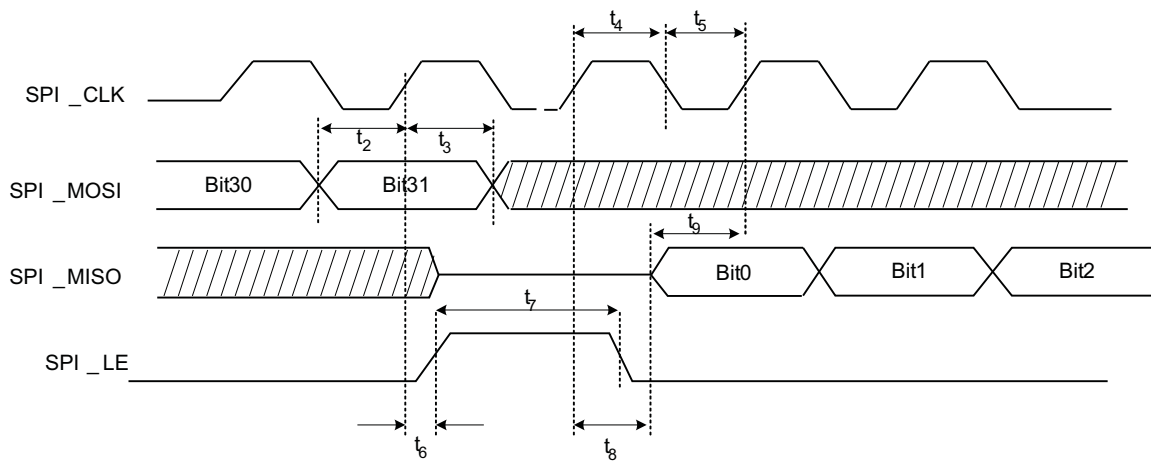


Figure 13. Timing Diagram for SPI Read Command

SPI Bus Timing Characteristics

PARAMETER		MIN	TYP	MAX	UNIT
f_{Clock}	Clock Frequency for the SPI_CLK			20	MHz
t_1	SPI_LE to SPI_CLK setup time	10			ns
t_2	SPI_MOSI to SPI_CLK setup time	10			ns
t_3	SPI_MOSI to SPI_CLK hold time	10			ns
t_4	SPI_CLK high duration	25			ns
t_5	SPI_CLK low duration	25			ns
t_6	SPI_CLK to SPI_LE Setup time	10			ns
t_7	SPI_LE Pulse Width	20			ns
t_8	SPI_MISO to SPI_CLK Data Valid (First Valid Bit after LE)	10			ns

DEVICE CONFIGURATION

The Functional Description Section described three different functional blocks contained within the CDCE18005. [Figure 14](#) depicts these blocks along with a high-level functional block diagram of the circuit elements comprising each block. The balance of this section focuses on a detailed discussion of each functional block from the perspective of how to configure them.

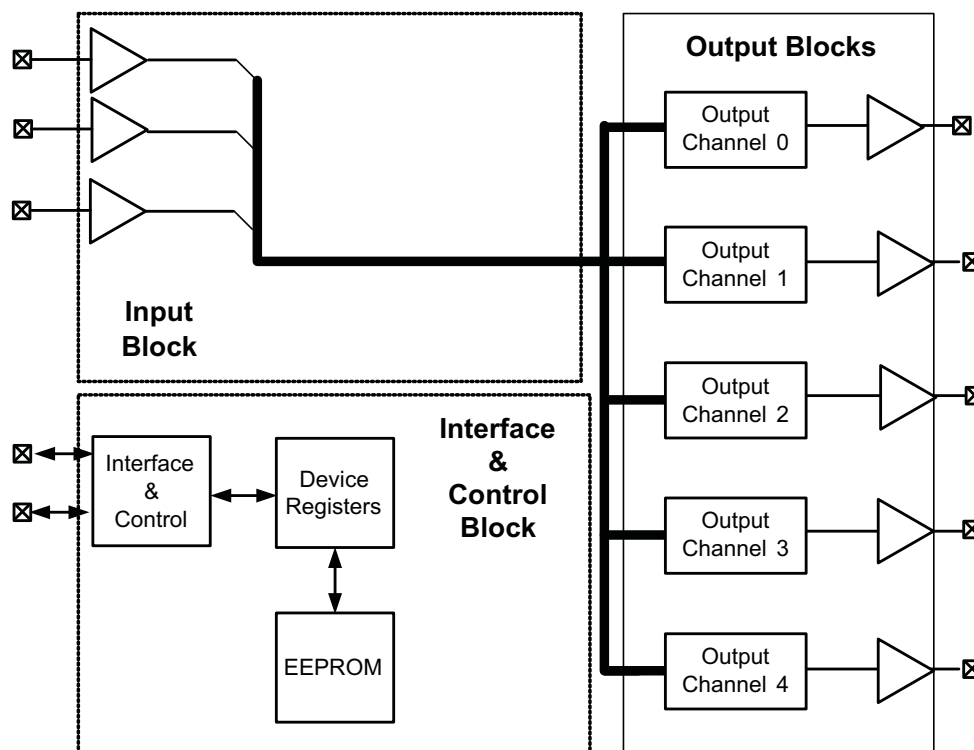


Figure 14. CDCE18005 Circuit Blocks

Throughout this section, references to Device Register memory locations follow the following convention:

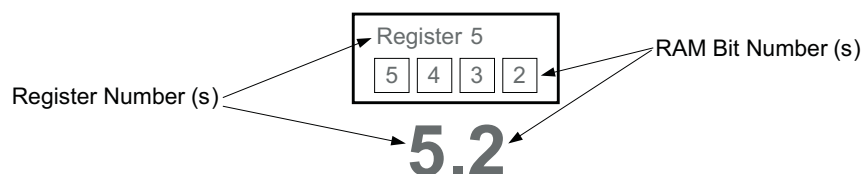


Figure 15. Device Register Reference Convention

INTERFACE AND CONTROL BLOCK

The Interface & Control Block includes a SPI interface, four control pins, a non-volatile memory array in which the device stores default configuration data, and an array of device registers implemented in Static RAM. This RAM, also called the device registers, configures all hardware within the CDCE18005.

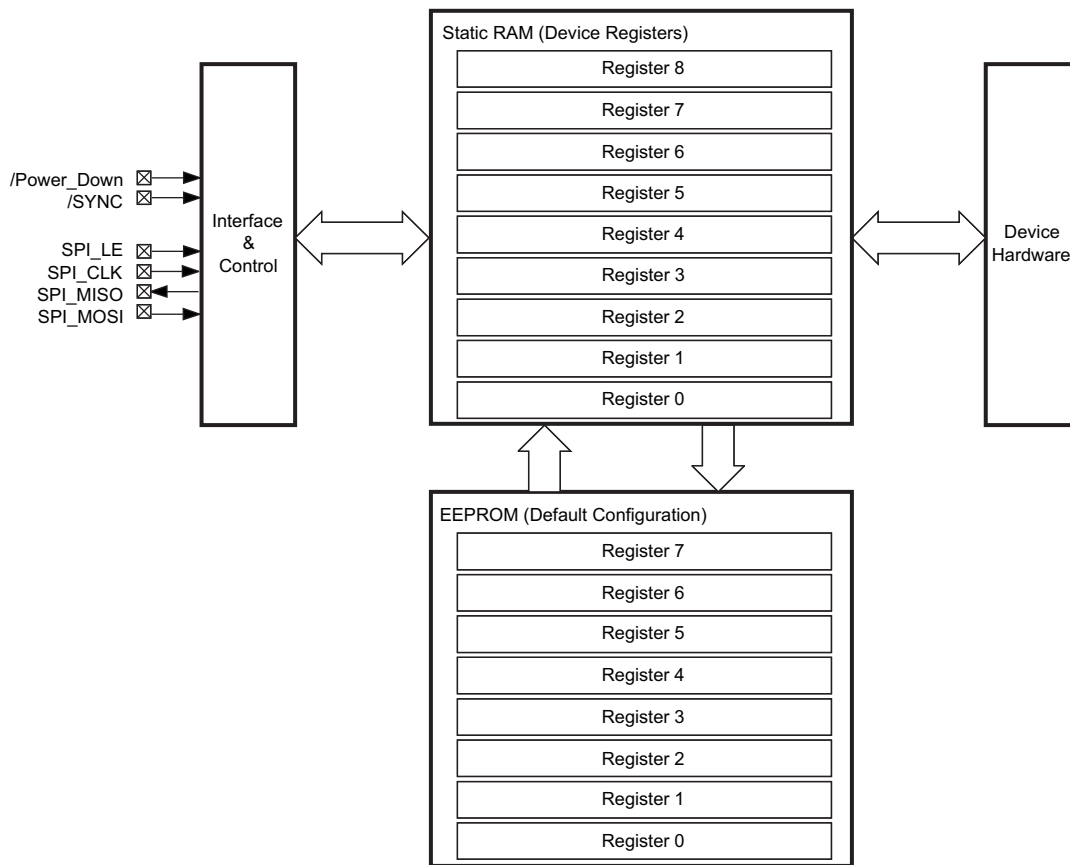


Figure 16. CDCE18005 Interface and Control Block

SPI (Serial Peripheral Interface)

The serial interface of CDCE18005 is a simple bidirectional SPI interface for writing and reading to and from the device registers. It implements a low speed serial communications link in a master/slave topology in which the CDCE18005 is a slave. The SPI consists of four signals:

- **SPI_CLK:** Serial Clock (Output from Master) – the CDCE18005 clocks data in and out on the rising edge of SPI_CLK. Data transitions therefore occur on the falling edge of the clock.
- **SPI_MOSI:** Master Output Slave Input (Output from Master).
- **SPI_MISO:** Master Input Slave Output (Output from Slave).
- **SPI_LE:** Latch Enable (Output from Master). The falling edge of SPI_LE initiates a transfer. If SPI_LE is high, no data transfer can take place.

The CDCE18005 implements data fields that are 28-bits wide. In addition, it contains 9 registers, each comprising a 28 bit data field. Therefore, accessing the CDCE18005 requires that the host program append a 4-bit address field to the front of the data field as follows:

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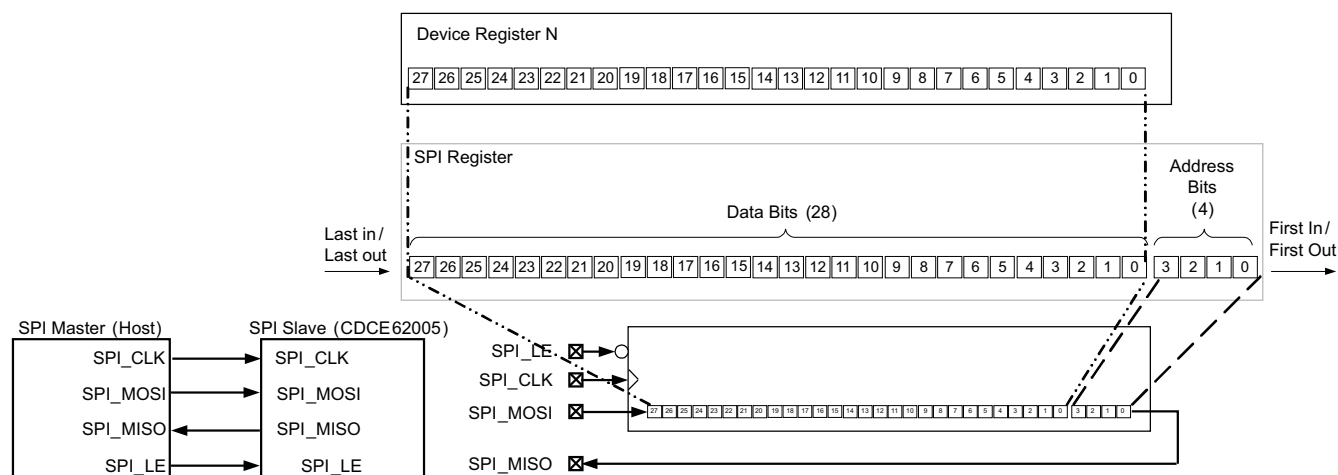
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Figure 17. CDCE18005 SPI Communications Format

CDCE18005 SPI Command Structure

The CDCE18005 supports four commands issued by the Master via the SPI:

- Write to RAM
- Read Command
- Copy RAM to EEPROM – unlock
- Copy RAM to EEPROM – lock

Table 3 provides a summary of the CDCE18005 SPI command structure. The host (master) constructs a Write to RAM command by specifying the appropriate register address in the address field and appends this value to the beginning of the data field. Therefore, a valid command stream must include 32 bits, transmitted LSB first. The host must issue a Read Command to initiate a data transfer from the CDCE18005 back to the host. This command specifies the address of the register of interest in the data field.

Table 3. CDCE18005 SPI Command Structure

			Data Field (28 Bits)																												Addr Field (4 Bits)					
Register	Operation	NVM	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	3	2	1	0		
0	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	0	0	0	
1	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	0	0	1	
2	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	0	1	0	
3	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	0	1	1	
4	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	1	0	0	
5	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	1	0	1	
6	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	1	1	0	
7	Write to RAM	Yes	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	0	1	1	1	
8	Status/Control	No	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	1	0	0	0	
Instruction	Read Command	No	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	A	A	A	1	1	1	0
Instruction	RAM EEPROM	Unlock ⁽¹⁾	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	
Instruction	RAM EEPROM	Lock	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	0	0	0	1	1	1	1	1		

(1) **CAUTION:** After execution of this command, the EEPROM is permanently locked. After locking the EEPROM, device configuration can only be changed via Write to RAM after power-up; however, the EEPROM can no longer be changed

The CDCE18005 on-board EEPROM has been factory preset to the default settings listed in the table below.

REGISTER	DEFAULT SETTING
REG0000	8140000
REG0001	8140000
REG0002	8140000
REG0003	8140000
REG0004	8140000
REG0005	0000096
REG0006	0000000
REG0007	9400000
REG0008 (RAM)	8000580

The default configurations programmed in the device is set to: PRI_REF (set to LVPECL) feeding all outputs. Output dividers are set to DIVIDE by 1. All output dividers are set to LVPECL

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Writing to the CDCE18005

Figure 18 illustrates a Write to RAM operation. Notice that the latching of the first data bit in the data stream (Bit 0) occurs on the first rising edge of SPI_CLK after SPI_LE transitions from a high to a low. For the CDCE18005, data transitions occur on the falling edge of SPI_CLK. A rising edge on SPI_LE signals to the CDCE18005 that the transmission of the last bit in the stream (Bit 31) has occurred.

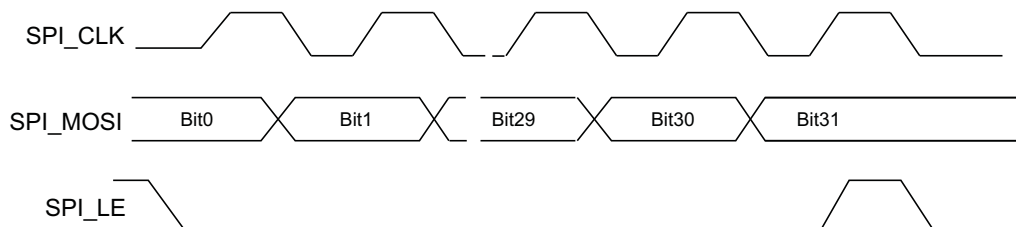


Figure 18. CDCE18005 SPI Write Operation

Reading from the CDCE18005

Figure 19 shows how the CDCE18005 executes a Read Command. The SPI master first issues a Read Command to initiate a data transfer from the CDCE18005 back to the host (see Table 6). This command specifies the address of the register of interest. By transitioning SPI_LE from a low to a high, the CDCE18005 resolves the address specified in the appropriate bits of the data field. The host drives SPI_LE low and the CDCE18005 presents the data present in the register specified in the Read Command on SPI_MISO.

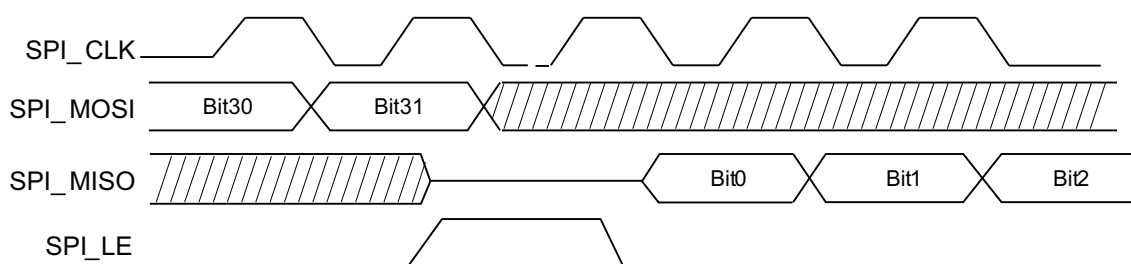


Figure 19. CDCE18005 Read Operation

Writing to EEPROM

After the CDCE18005 detects a power-up and completes a reset cycle, it copies the contents of the on-board EEPROM into the Device Registers. Therefore, the CDCE18005 initializes into a known state pre-defined by the user. The host issues one of two special commands shown in Table 6 to copy the contents of Device Registers 0 through 7 (a total of 184 bits) into EEPROM. They include:

- Copy RAM to EEPROM – Unlock, Execution of this command can happen many times.
- Copy RAM to EEPROM – Lock: Execution of this command can happen only once; after which the EEPROM is **permanently locked**.

After either command is initiated, power must remain stable and the host must not access the CDCE18005 for at least 50 ms to allow the EEPROM to complete the write cycle and to avoid the possibility of EEPROM corruption.

Device Registers: Register 0
Table 4. CDCE18005 Register 0 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION									
0		A0		Address 0							0		
1		A1		Address 1							0		
2		A2		Address 2							0		
3		A3		Address 3							0		
4	0	RESERVED		Always Set to "0" for Proper Operation							EEPROM		
5	1	RESERVED									EEPROM		
6	2	RESERVED									EEPROM		
7	3	RESERVED									EEPROM		
8	4	OUTMUX0SELX	Output 0	OUTPUT MUX "0" Select. Selects the Signal driving Output Divider "0" (X,Y) = 00: PRI_IN, 01:SEC_IN, 10:SMART_MUX, 11:Reserved							EEPROM		
9	5	OUTMUX0SELY	Output 0								EEPROM		
10	6	PH0ADJC0	Output 0	Coarse phase adjust select for output divider "0"							EEPROM		
11	7	PH0ADJC1	Output 0								EEPROM		
12	8	PH0ADJC2	Output 0								EEPROM		
13	9	PH0ADJC3	Output 0								EEPROM		
14	10	PH0ADJC4	Output 0								EEPROM		
15	11	PH0ADJC5	Output 0								EEPROM		
16	12	PH0ADJC6	Output 0								EEPROM		
17	13	OUT0DIVRSEL0	Output 0	OUTPUT DIVIDER "0" Ratio Select							EEPROM		
18	14	OUT0DIVRSEL1	Output 0								EEPROM		
19	15	OUT0DIVRSEL2	Output 0								EEPROM		
20	16	OUT0DIVRSEL3	Output 0								EEPROM		
21	17	OUT0DIVRSEL4	Output 0								EEPROM		
22	18	OUT0DIVRSEL5	Output 0								EEPROM		
23	19	OUT0DIVRSEL6	Output 0								EEPROM		
24	20	OUT0DIVSEL	Output 0	When set to "0", the divider is disabled When set to "1", the divider is enabled							EEPROM		
25	21	HiSWINGLVPECL0	Output 0	High Swing LVPECL When set to "1" and Normal Swing when set to "0" – If LVCMOS or LVDS is selected the Output swing will stay at the same level. – If LVPECL buffer is selected the Output Swing will be 30% higher if this bit is set to "1" and Normal LVPECL if it is set to "0".							EEPROM		
26	22	CMOSMODE0PX	Output 0	LVCMOS mode select for OUTPUT "0" Positive Pin.							EEPROM		
27	23	CMOSMODE0PY	Output 0	(X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM		
28	24	CMOSMODE0NX	Output 0	LVCMOS mode select for OUTPUT "0" Negative Pin.							EEPROM		
29	25	CMOSMODE0NY	Output 0	(X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM		
30	26	OUTBUFSEL0X	Output 0	OUTPUT TYPE		RAM BITS						EEPROM	
31	27	OUTBUFSEL0Y	Output 0	LVPECL		22	23	24	25	26		27	EEPROM
				LVDS		0	1	0	1	1		1	
				LVCMOS		See Settings Above*				0		0	
				Output Disabled		0	1	0	1	1		0	
* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs													

* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs

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Device Registers: Register 1

Table 5. CDCE18005 Register 1 Bit Definitions

SPI BIT	RA M BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION														
0		A0		Address 0							1							
1		A1		Address 1							0							
2		A2		Address 2							0							
3		A3		Address 3							0							
4	0	RESERVED		Always St "0" for Proper Operation							EEPROM							
5	1	RESERVED									EEPROM							
6	2	RESERVED									EEPROM							
7	3	RESERVED									EEPROM							
8	4	OUTMUX1SELX	Output 1	OUTPUT MUX "1" Select. Selects the Signal driving Output Divider "1" (X,Y) = 00: PRI_IN, 01:SEC_IN, 10:SMART_MUX, 11:Reserved							EEPROM							
9	5	OUTMUX1SELY	Output 1								EEPROM							
10	6	PH1ADJC0	Output 1	Coarse phase adjust select for output divider "1"							EEPROM							
11	7	PH1ADJC1	Output 1								EEPROM							
12	8	PH1ADJC2	Output 1								EEPROM							
13	9	PH1ADJC3	Output 1								EEPROM							
14	10	PH1ADJC4	Output 1								EEPROM							
15	11	PH1ADJC5	Output 1								EEPROM							
16	12	PH1ADJC6	Output 1								EEPROM							
17	13	OUT1DIVRSEL0	Output 1	OUTPUT DIVIDER "1" Ratio Select							EEPROM							
18	14	OUT1DIVRSEL1	Output 1								EEPROM							
19	15	OUT1DIVRSEL2	Output 1								EEPROM							
20	16	OUT1DIVRSEL3	Output 1								EEPROM							
21	17	OUT1DIVRSEL4	Output 1								EEPROM							
22	18	OUT1DIVRSEL5	Output 1								EEPROM							
23	19	OUT1DIVRSEL6	Output 1								EEPROM							
24	20	OUT1DIVSEL	Output 1	When set to "0", the divider is disabled When set to "1", the divider is enabled							EEPROM							
25	21	HiSWINGLVPECL1	Output 1	High Swing LVPECL When set to "1" and Normal Swing when set to "0" – If LVCMOS or LVDS is selected the Output swing will stay at the same level. – If LVPECL buffer is selected the Output Swing will be 30% higher if this bit is set to "1" and Normal LVPECL if it is set to "0".							EEPROM							
26	22	CMOSMODE1PX	Output 1	LVCMOS mode select for OUTPUT "1" Positive Pin.							EEPROM							
27	23	CMOSMODE1PY	Output 1	(X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM							
28	24	CMOSMODE1NX	Output 1	LVCMOS mode select for OUTPUT "1" Negative Pin.							EEPROM							
29	25	CMOSMODE1NY	Output 1	(X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM							
30	26	OUTBUFSEL1X	Output 1	31	27	OUTBUFSEL1Y	Output 1	OUTPUT TYPE		RAM BITS							EEPROM	
																		EEPROM
* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs																		

* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs

Device Registers: Register 2
Table 6. CDCE18005 Register 2 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION									
0		A0		Address 0							0		
1		A1		Address 1							1		
2		A2		Address 2							0		
3		A3		Address 3							0		
4	0	RESERVED		Always Set to "0" for Proper Operation							EEPROM		
5	1	RESERVED									EEPROM		
6	2	RESERVED									EEPROM		
7	3	RESERVED									EEPROM		
8	4	OUTMUX2SELX	Output 2	OUTPUT MUX "2" Select. Selects the Signal driving Output Divider "2" (X,Y) = 00: PRI_IN, 01:SEC_IN, 10:SMART_MUX, 11:Reserved							EEPROM		
9	5	OUTMUX2SELY	Output 2								EEPROM		
10	6	PH2ADJC0	Output 2	Coarse phase adjust select for output divider "2"							EEPROM		
11	7	PH2ADJC1	Output 2								EEPROM		
12	8	PH2ADJC2	Output 2								EEPROM		
13	9	PH2ADJC3	Output 2								EEPROM		
14	10	PH2ADJC4	Output 2								EEPROM		
15	11	PH2ADJC5	Output 2								EEPROM		
16	12	PH2ADJC6	Output 2								EEPROM		
17	13	OUT2DIVRSEL0	Output 2	OUTPUT DIVIDER "2" Ratio Select							EEPROM		
18	14	OUT2DIVRSEL1	Output 2								EEPROM		
19	15	OUT2DIVRSEL2	Output 2								EEPROM		
20	16	OUT2DIVRSEL3	Output 2								EEPROM		
21	17	OUT2DIVRSEL4	Output 2								EEPROM		
22	18	OUT2DIVRSEL5	Output 2								EEPROM		
23	19	OUT2DIVRSEL6	Output 2								EEPROM		
24	20	OUT2DIVSEL	Output 2	When set to "0", the divider is disabled When set to "1", the divider is enabled							EEPROM		
25	21	HiSWINGLVPEC2	Output 2	High Swing LVPECL When set to "1" and Normal Swing when set to "0" – If LVCMOS or LVDS is selected the Output swing will stay at the same level. – If LVPECL buffer is selected the Output Swing will be 30% higher if this bit is set to "1" and Normal LVPECL if it is set to "0".							EEPROM		
26	22	CMOSMODE2PX	Output 2	LVCMOS mode select for OUTPUT "2" Positive Pin. (X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM		
27	23	CMOSMODE2PY	Output 2								EEPROM		
28	24	CMOSMODE2NX	Output 2	LVCMOS mode select for OUTPUT "2" Negative Pin. (X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM		
29	25	CMOSMODE2NY	Output 2								EEPROM		
30	26	OUTBUFSEL2X	Output 2	OUTPUT TYPE		RAM BITS						EEPROM	
31	27	OUTBUFSEL2Y	Output 2		22	23	24	25	26	27		EEPROM	
				LVPECL	0	0	0	0	0	1			
				LVDS	0	1	0	1	1	1			
				LVCMOS	See Settings Above*					0			0
				Output Disabled	0	1	0	1	1	0			
* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs													

* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs

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Device Registers: Register 3

Table 7. CDCE18005 Register 3 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION										
0		A0		Address 0							1			
1		A1		Address 1							1			
2		A2		Address 2							0			
3		A3		Address 3							0			
4	0	RESERVED		Always Set to "0" for Proper Operation							EEPROM			
5	1	RESERVED									EEPROM			
6	2	RESERVED									EEPROM			
7	3	RESERVED									EEPROM			
8	4	OUTMUX3SELX	Output 3	OUTPUT MUX "3" Select. Selects the Signal driving Output Divider "3" (X,Y) = 00: PRI_IN, 01:SEC_IN, 10:SMART_MUX, 11:Reserved							EEPROM			
9	5	OUTMUX3SELY	Output 3								EEPROM			
10	6	PH3ADJC0	Output 3	Coarse phase adjust select for output divider "3"							EEPROM			
11	7	PH3ADJC1	Output 3								EEPROM			
12	8	PH3ADJC2	Output 3								EEPROM			
13	9	PH3ADJC3	Output 3								EEPROM			
14	10	PH3ADJC4	Output 3								EEPROM			
15	11	PH3ADJC5	Output 3								EEPROM			
16	12	PH3ADJC6	Output 3								EEPROM			
17	13	OUT3DIVRSEL0	Output 3	OUTPUT DIVIDER "3" Ratio Select							EEPROM			
18	14	OUT3DIVRSEL1	Output 3								EEPROM			
19	15	OUT3DIVRSEL2	Output 3								EEPROM			
20	16	OUT3DIVRSEL3	Output 3								EEPROM			
21	17	OUT3DIVRSEL4	Output 3								EEPROM			
22	18	OUT3DIVRSEL5	Output 3								EEPROM			
23	19	OUT3DIVRSEL6	Output 3								EEPROM			
24	20	OUT3DIVSEL	Output 3	When set to "0", the divider is disabled When set to "1", the divider is enabled							EEPROM			
25	21	HiSWINGLVPEC3	Output 3	High Swing LVPECL When set to "1" and Normal Swing when set to "0" – If LVCMOS or LVDS is selected the Output swing will stay at the same level. – If LVPECL buffer is selected the Output Swing will be 30% higher if this bit is set to "1" and Normal LVPECL if it is set to "0".							EEPROM			
26	22	CMOSMODE3PX	Output 3	LVCMOS mode select for OUTPUT "3" Positive Pin. (X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM			
27	23	CMOSMODE3PY	Output 3								EEPROM			
28	24	CMOSMODE3NX	Output 3	LVCMOS mode select for OUTPUT "3" Negative Pin. (X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM			
29	25	CMOSMODE3NY	Output 3								EEPROM			
30	26	OUTBUFSEL3X	Output 3	OUTPUT TYPE			RAM BITS					EEPROM		
31	27	OUTBUFSEL3Y	Output 3				22	23	24	25		26	27	EEPROM
				LVPECL			0	0	0	0		0	1	
				LVDS			0	1	0	1		1	1	
				LVCMOS			See Settings Above*					0	0	
				Output Disabled			0	1	0	1		1	0	
* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs														

Device Registers: Register 4
Table 8. CDCE18005 Register 4 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION								
0		A0		Address 0							0	
1		A1		Address 1							0	
2		A2		Address 2							1	
3		A3		Address 3							0	
4	0	RESERVED		Must be set to "0" for proper operation							EEPROM	
5	1	RESERVED									EEPROM	
6	2	RESERVED									EEPROM	
7	3	RESERVED									EEPROM	
8	4	OUTMUX4SELX	Output 4	OUTPUT MUX "4" Select. Selects the Signal driving Output Divider "4" (X,Y) = 00: PRI_IN, 01:SEC_IN, 10:SMART_MUX, 11:Reserved							EEPROM	
9	5	OUTMUX4SELY	Output 4								EEPROM	
10	6	PH4ADJC0	Output 4	Coarse phase adjust select for output divider "4"							EEPROM	
11	7	PH4ADJC1	Output 4								EEPROM	
12	8	PH4ADJC2	Output 4								EEPROM	
13	9	PH4ADJC3	Output 4								EEPROM	
14	10	PH4ADJC4	Output 4								EEPROM	
15	11	PH4ADJC5	Output 4								EEPROM	
16	12	PH4ADJC6	Output 4								EEPROM	
17	13	OUT4DIVRSEL0	Output 4	OUTPUT DIVIDER "4" Ratio Select							EEPROM	
18	14	OUT4DIVRSEL1	Output 4								EEPROM	
19	15	OUT4DIVRSEL2	Output 4								EEPROM	
20	16	OUT4DIVRSEL3	Output 4								EEPROM	
21	17	OUT4DIVRSEL4	Output 4								EEPROM	
22	18	OUT4DIVRSEL5	Output 4								EEPROM	
23	19	OUT4DIVRSEL6	Output 4								EEPROM	
24	20	OUT4DIVSEL	Output 4	When set to "0", the divider is disabled When set to "1", the divider is enabled							EEPROM	
25	21	HiSWINGLVPEC4	Output 4	High Swing LVPECL When set to "1" and Normal Swing when set to "0" – If LVCMOS or LVDS is selected the Output swing will stay at the same level. – If LVPECL buffer is selected the Output Swing will be 30% higher if this bit is set to "1" and Normal LVPECL if it is set to "0".							EEPROM	
26	22	CMOSMODE4PX	Output 4	LVCMOS mode select for OUTPUT "4" Positive Pin. (X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM	
27	23	CMOSMODE4PY	Output 4								EEPROM	
28	24	CMOSMODE4NX	Output 4	LVCMOS mode select for OUTPUT "3" Negative Pin. (X,Y)=00:Active, 10:Inverting, 11:Low, 01:3-State							EEPROM	
29	25	CMOSMODE4NY	Output 4								EEPROM	
30	26	OUTBUFSEL4X	Output 4	OUTPUT TYPE 222324252627 LVPECL000001 LVDS010111 LVCMOSSee Settings Above*00 Output Disabled010110								EEPROM
31	27	OUTBUFSEL4Y	Output 4									EEPROM
* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs												

* Use Description for Bits 22,23,24 and 25 for setting the LVCMOS Outputs

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Device Registers: Register 5

Table 9. CDCE18005 Register 5 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION	
0		A0		Address 0	1
1		A1		Address 1	0
2		A2		Address 2	1
3		A3		Address 3	0
4	0	INBUFSELX	INBUFSELX	Input Buffer Select (LVPECL, LVDS or LVCMOS) XY(01) LVPECL, (11) LVDS, (00) LVCMOS- Input is Positive Pin	EEPROM
5	1	INBUFSELY	INBUFSELY		EEPROM
6	2	SYNCSEL1	Output Divider Synchronizati on	SYNCSEL(1,2)= 10 :Output divider sync to Primary input	EEPROM
7	3	SYNCSEL2		SYNCSEL(1,2)= 01 :Output divider sync to Secondary input SYNCSEL(1,2)= 00 :Output divider sync to Auxiliary input	EEPROM
8	4	RESERVED		Always Set to "1" for Proper Operation	EEPROM
9	5	RESERVED		Always Set to "0" for Proper Operation	EEPROM
10	6	ACDCSEL	Input Buffers	If Set to "1" DC Termination, If set to "0" AC Termination	EEPROM
11	7	HYSTEN	Input Buffers	If Set to "1" Input Buffers Hysteresis Enabled. It is not recommended that Hysteresis be disabled.	EEPROM
12	8	PRI_TERMSEL	Input Buffers	If Set to "0" Primary Input Buffer Internal Termination Enabled If set to "1" Primary Internal Termination circuitry Disabled	EEPROM
13	9	PRIINVBB	Input Buffers	If Set to "1" Primary Input Negative Pin Biased with Internal VBB Voltage.	EEPROM
14	10	SECINVBB	Input Buffers	If Set to "1" Secondary Input Negative Pin Biased with Internal VBB Voltage	EEPROM
15	11	FAILSAFE	Input Buffers	If Set to "1" Fail Safe is Enabled for all Input Buffers configured as LVDS, DC Coupling only.	EEPROM
16	12	RESERVED	- - - -	Must be set to "0" for proper operation	EEPROM
17	13	RESERVED			EEPROM
18	14	RESERVED			EEPROM
19	15	RESERVED			EEPROM
20	16	RESERVED			EEPROM
21	17	RESERVED			EEPROM
22	18	RESERVED			EEPROM
23	19	RESERVED			EEPROM
24	20	RESERVED			EEPROM
25	21	RESERVED			EEPROM
26	22	RESERVED			EEPROM
27	23	RESERVED			EEPROM
28	24	RESERVED			EEPROM
29	25	RESERVED			EEPROM
30	26	RESERVED			EEPROM
31	27	RESERVED			EEPROM

Device Registers: Register 6
Table 10. CDCE18005 Register 6 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION	
0		A0		Address 0	0
1		A1		Address 1	1
2		A2		Address 2	1
3		A3		Address 3	0
4	0	RESERVED		Must be set to "0"	EEPROM
5	1	RESERVED			EEPROM
6	2	RESERVED			EEPROM
7	3	RESERVED			EEPROM
8	4	RESERVED			EEPROM
9	5	RESERVED			EEPROM
10	6	RESERVED			EEPROM
11	7	RESERVED			EEPROM
12	8	RESERVED			EEPROM
13	9	RESERVED			EEPROM
14	10	RESERVED			EEPROM
15	11	RESERVED			EEPROM
16	12	SEC_TERMSEL	Input Buffers	If Set to "0" Secondary Input Buffer Internal Termination Enabled If set to "1" Secondary Internal Termination circuitry Disabled	EEPROM
17	13	RESERVED		Must be set to "0"	EEPROM
18	14	RESERVED			EEPROM
19	15	RESERVED			EEPROM
20	16	RESERVED			EEPROM
21	17	RESERVED			EEPROM
22	18	RESERVED			EEPROM
23	19	RESERVED			EEPROM
24	20	RESERVED			EEPROM
25	21	RESERVED			EEPROM
26	22	RESERVED			EEPROM
27	23	RESERVED			EEPROM
28	24	AUXOUTEN	Output AUX	Enable Auxiliary Output when set to "1"	EEPROM
29	25	AUXFEEDSEL	Output AUX	Select the Output that will driving the AUX Output; Low for Selecting Output Divider "2" and High for Selecting Output Divider "3"	EEPROM
30	26	RESERVED		Must be set to "0"	EEPROM
31	27	RESERVED		Must be set to "0"	EEPROM

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Device Registers: Register 7

Table 11. CDCE18005 Register 7 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION	
0		A0		Address 0	1
1		A1		Address 1	1
2		A2		Address 2	1
3		A3		Address 3	0
4	0	RESERVED		Always Set to "0" for Proper Operation	EEPROM
5	1	RESERVED			EEPROM
6	2	RESERVED			EEPROM
7	3	RESERVED			EEPROM
8	4	RESERVED			EEPROM
9	5	RESERVED			EEPROM
10	6	RESERVED			EEPROM
11	7	RESERVED			EEPROM
12	8	RESERVED			EEPROM
13	9	RESERVED			EEPROM
14	10	RESERVED			EEPROM
15	11	RESERVED			EEPROM
16	12	RESERVED			EEPROM
17	13	RESERVED			EEPROM
18	14	RESERVED			EEPROM
19	15	RESERVED			EEPROM
20	16	RESERVED			EEPROM
21	17	RESERVED			EEPROM
22	18	RESERVED			EEPROM
23	19	RESERVED			EEPROM
24	20	RESERVED			EEPROM
25	21	RESERVED			EEPROM
26	22	TESTMUX1	Diagnostics	Set to "1"	EEPROM
27	23	RESERVED		Always Set to "0" for Proper Operation	EEPROM
28	24	TEXTMUX2	Diagnostics	Set to "1"	EEPROM
29	25	RESERVED		Always Set to "0" for Proper Operation	EEPROM
30	26	EPUNLOCK	Status	EEPROM Unlock	RAM
31	27	EPSTATUS	Status	EEPROM Status	RAM

Device Registers: Register 8
Table 12. CDCE18005 Register 8 Bit Definitions

SPI BIT	RAM BIT	BIT NAME	RELATED BLOCK	DESCRIPTION/FUNCTION	
0		A0		Address 0	0
1		A1		Address 1	0
2		A2		Address 2	0
3		A3		Address 3	1
4	0	RESERVED		<i>TI Test Registers. For TI Use Only</i>	RAM
5	1	RESERVED			RAM
6	2	RESERVED			RAM
7	3	RESERVED			RAM
8	4	RESERVED			RAM
9	5	RESERVED			RAM
10	6	RESERVED			RAM
11	7	$\overline{\text{SLEEP}}$	Status	Set Device Sleep mode On when set to "0", Normal Mode when set to "1"	RAM
12	8	$\overline{\text{SYNC}}$	Status	If set to "0" this bit forces $\overline{\text{SYNC}}$; Set to "1" to exit the Synchronization State.	RAM
13	9	RESERVED			RAM
14	10	VERSION0	Tie off	Silicon Revision	RAM
15	11	VERSION1	Tie off	Silicon Revision	RAM
16	12	VERSION2	Tie off	Silicon Revision	RAM
17	13	RESERVED		<i>TI Test Registers. For TI Use Only</i>	RAM
18	14	RESERVED			RAM
19	15	RESERVED			RAM
20	16	RESERVED			RAM
21	17	RESERVED			RAM
22	18	RESERVED			RAM
23	19	RESERVED			RAM
24	20	RESERVED			RAM
25	21	RESERVED			RAM
26	22	RESERVED			RAM
27	23	RESERVED			RAM
28	24	RESERVED			RAM
29	25	RESERVED			RAM
30	26	RESERVED			RAM
31	27	RESERVED			RAM

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Device Control

Figure 20 provides a conceptual explanation of the CDCE18005 Device operation. Table 13 defines how the device behaves in each of the operational states.

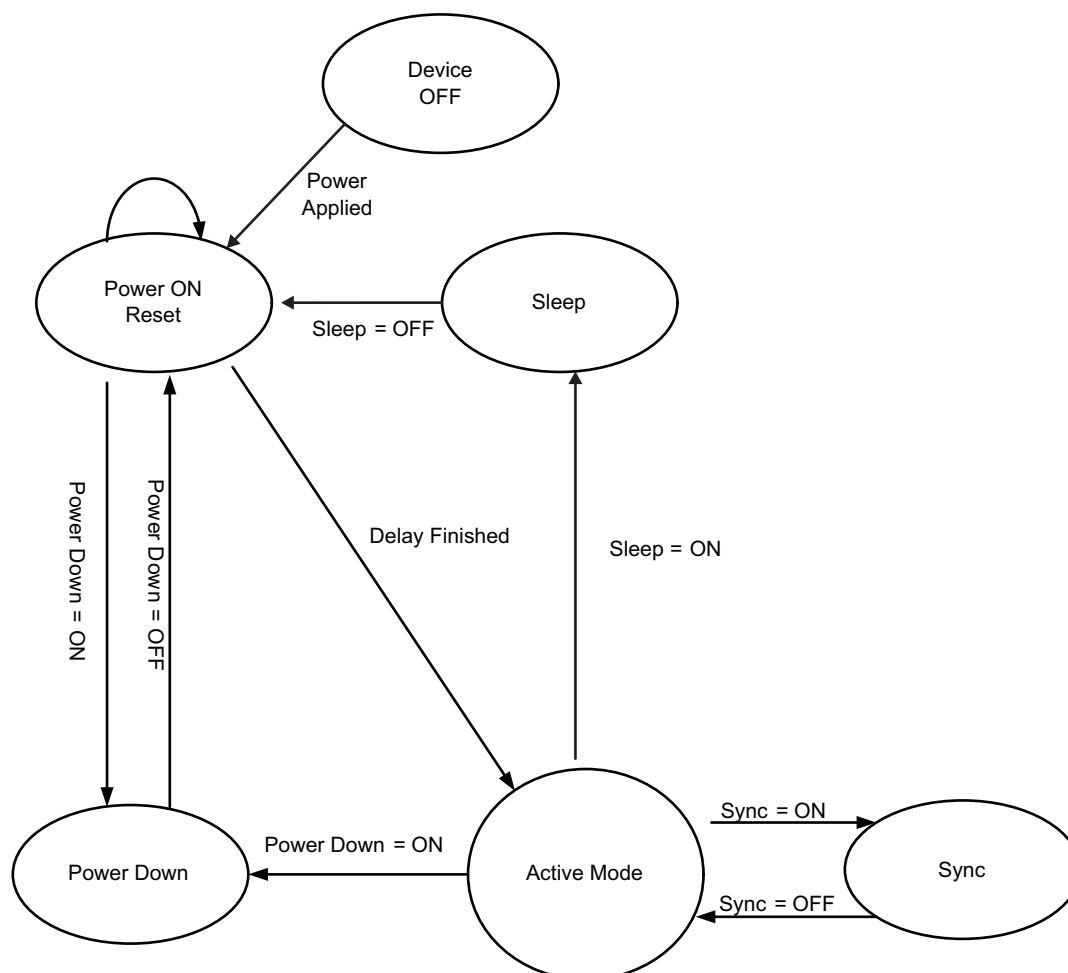


Figure 20. CDCE18005 Device State Control Diagram

Table 13. CDCE18005 Device State Definitions

State	Device Behavior	Entered Via	Exited Via	Status		
				SPI Port	Output Divider	Output Buffer
Power-On Reset	After device power supply reaches approximately 2.35V, the contents of EEPROM are copied into the Device Registers, thereby initializing the device hardware .	Power applied to the device or upon exit from Power Down State via the Power_Down pin set HIGH.	Power On Reset and EEPROM loading delays are finished OR the Power_Down pin is set LOW.	OFF	Disabled	OFF
Active Mode	Normal Operation	Sync = OFF (from Sync State).	Sync, Power Down, Sleep, or Manual Recalibration activated.	ON	Disabled or Enabled	Disabled or Enabled
Power Down	Used to shut down all hardware and Resets the device after exiting the Power Down State. Therefore, the EEPROM contents will eventually be copied into RAM after the Power Down State is exited.	Power_Down pin is pulled LOW.	Power_Down pin is pulled HIGH.	ON	Disabled	Disabled
Sleep	Identical to the Power Down State except the EEPROM contents are not copied into RAM.	SLEEP bit in device register 8 bit 7 is set LOW.	SLEEP bit in device register 8 bit 7 is set HIGH.	ON	Disabled	Disabled

Table 13. CDCE18005 Device State Definitions (continued)

State	Device Behavior	Entered Via	Exited Via	Status		
				SPI Port	Output Divider	Output Buffer
Sync	Sync synchronizes all output dividers so that they begin counting at the same time. Note: this operation is performed automatically each time a divider register is accessed.	$\overline{\text{SYNC}}$ Bit in device register 8 bit 8 is set LOW or $\overline{\text{SYNC}}$ pin is pulled LOW	$\overline{\text{SYNC}}$ Bit in device register 8 bit 8 is set HIGH or $\overline{\text{SYNC}}$ pin is pulled HIGH	ON	Disabled	Disabled

External Control Pins

Power_Down

The Power_Down pin places the CDCE18005 into the power down state. Additionally, the CDCE18005 loads the contents of the EEPROM into RAM after the Power_Down pin is de-asserted; therefore, it is used to initialize the device after power is applied. SPI_LE signal has to be HIGH in order for EEPROM to load correctly during the rising edge of Power_Down.

SYNC

The SYNC pin (Active LOW) has a complementary register location located in Device Register 8 bit 8. When enabled, Sync synchronizes all output dividers so that they begin counting simultaneously. Further, SYNC disables all outputs when in the active. State.

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INPUT BLOCK

The Input Block includes two Universal Input Buffers, an Auxiliary Input. The Input Block drives three different clock signals onto the Internal Clock Distribution Bus.

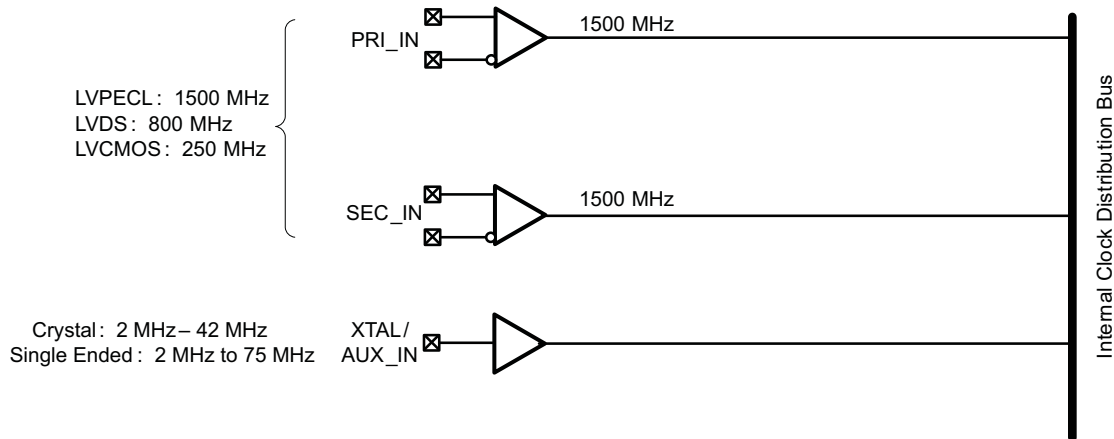


Figure 21. CDCE18005 Input Block With References to Registers

Universal Input Buffers (UIB)

Figure 22 shows the key elements of a universal input buffer. A UIB supports multiple formats along with different termination and coupling schemes. The CDCE18005 implements the UIB by including on board switched termination, a programmable bias voltage generator, and an output multiplexer. The CDCE18005 provides a high degree of configurability on the UIB to facilitate most existing clock input formats.

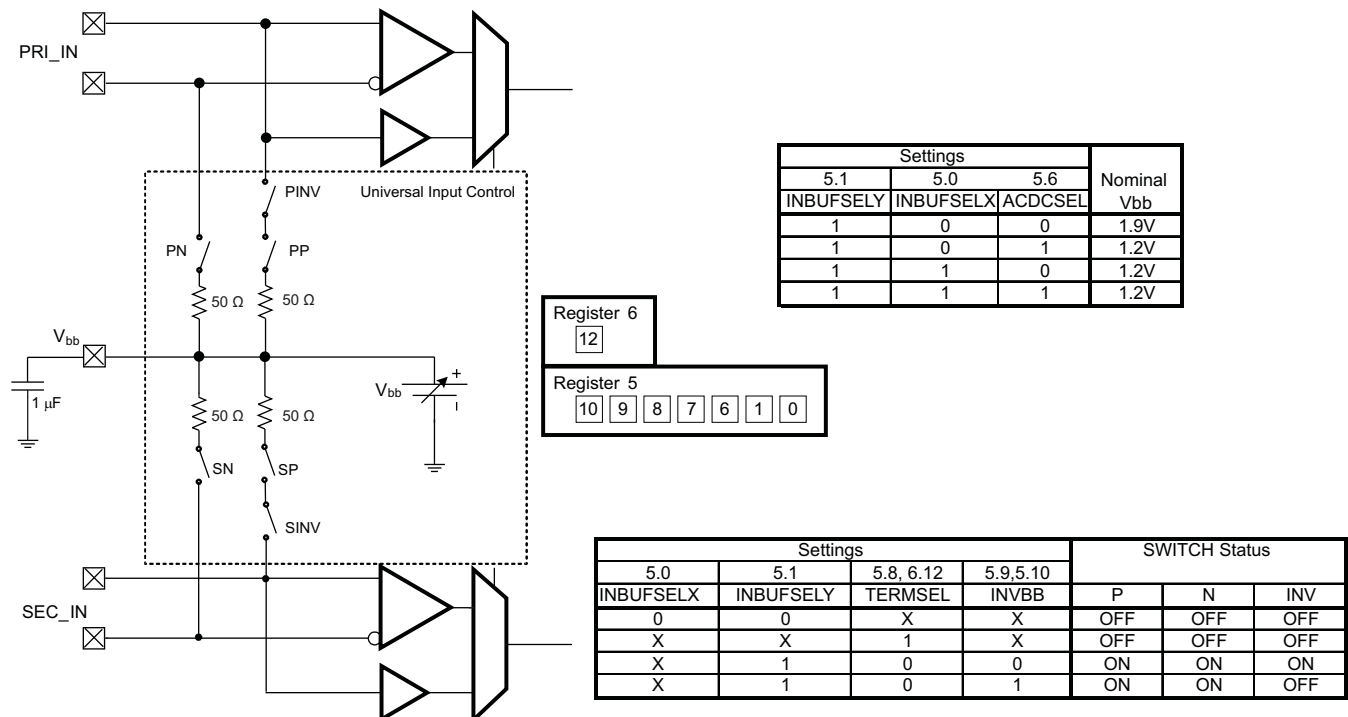


Figure 22. CDCE18005 Universal Input Buffer

Table 14 lists several settings for many possible clock input scenarios. Note that the two universal input buffers share the Vbb generator. Therefore, if both inputs use internal termination, they must use the same configuration mode (LVDS, LVPECL, or LVCMOS). If the application requires different modes (e.g. LVDS and LVPECL) then one of the two inputs must implement external termination.

Table 14. CDCE18005 Universal Input Buffer Configuration Matrix

PRI_IN CONFIGURATION MATRIX											
Register.Bit →	SETTINGS						CONFIGURATION				
	5.7	5.1	5.0	5.8	5.9	5.6	Hysteresis	Mode	Coupling	Termination	Vbb
Bit Name →	HYSTEN	INBUFSELY	INBUFSELX	PRI_TERMSEL	PRIINVBB	ACDCSEL					
	1	0	0	X	X	X	ENABLED	LVCMOS	DC	N/A	—
	1	1	0	0	0	0	ENABLED	LVPECL	AC	Internal	1.9V
	1	1	0	0	0	1	ENABLED	LVPECL	DC	Internal	1.2V
	1	1	0	1	X	X	ENABLED	LVPECL	—	External	—
	1	1	1	0	0	0	ENABLED	LVDS	AC	Internal	1.2V
	1	1	1	0	0	1	ENABLED	LVDS	DC	Internal	1.2V
	1	1	1	1	X	X	ENABLED	LVDS	—	External	—
	0	X	X	X	X	X	OFF	—	—	—	—
	1	X	X	X	X	X	ENABLED	—	—	—	—

SEC_IN CONFIGURATION MATRIX											
Register.Bit →	SETTINGS						CONFIGURATION				
	5.7	5.1	5.0	6.12	5.10	5.6	Hysteresis	Mode	Coupling	Termination	Vbb
Bit Name →	HYSTEN	INBUFSELY	INBUFSELX	SEC_TERMSEL	SECINVBB	ACDCSEL					
	1	0	0	X	X	X	ENABLED	LVCMOS	DC	N/A	—
	1	1	0	0	0	0	ENABLED	LVPECL	AC	Internal	1.9V
	1	1	0	0	0	1	ENABLED	LVPECL	DC	Internal	1.2V
	1	1	0	1	X	X	ENABLED	LVPECL	—	External	—
	1	1	1	0	0	0	ENABLED	LVDS	AC	Internal	1.2V
	1	1	1	0	0	1	ENABLED	LVDS	DC	Internal	1.2V
	1	1	1	1	X	X	ENABLED	LVDS	—	External	—
	0	X	X	X	X	X	OFF	—	—	—	—
	1	X	X	X	X	X	ENABLED	—	—	—	—

LVDS Fail Safe Mode

Differential data line receivers can switch on noise in the absence of an input signal. This occurs when the bus driver is turned off or the interconnect is damaged or missing. Traditionally the solution to this problem involves incorporating an external resistor network on the receiver input. This network applies a steady-state bias voltage to the input pins. The additional cost of the external components notwithstanding, the use of such a network lowers input signal magnitude and thus reduces the differential noise margin. The CDCE18005 provides internal failsafe circuitry on all LVDS inputs if enabled as shown in Table 15 for DC termination only.

Table 15. LVDS Failsafe Settings

Bit Name → Register.Bit →	FAILSAFE 5.11	LVDS Failsafe
	0	Disabled for all inputs
	1	Enabled for all inputs

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Auxiliary Input Port

The auxiliary input on the CDCE18005 is designed to connect to an AT-Cut Crystal with a total load capacitance (C_L) of 0 to 10 pF. One side of the crystal connects to Ground while the other side connects to the Auxiliary input of the device. The circuit works optimally between 20 to 40 MHz but it can accept crystals from 2 to 42 MHz.

Since the Auxiliary input operates between 0 and 2 V with a crystal, it can accept single-ended signals (e.g. LVCMOS). Electrically, it is equivalent to an LVCMOS input buffer with 10 pF of input capacitance.

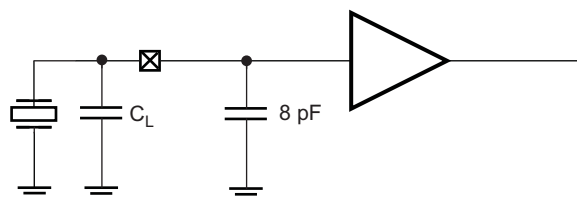


Figure 23. CDCE18005 Auxiliary Input Port

OUTPUT BLOCK

The output block includes five identical output channels. Each output channel comprises an output multiplexer, a clock divider module, and a universal output buffer as shown in Figure 24.

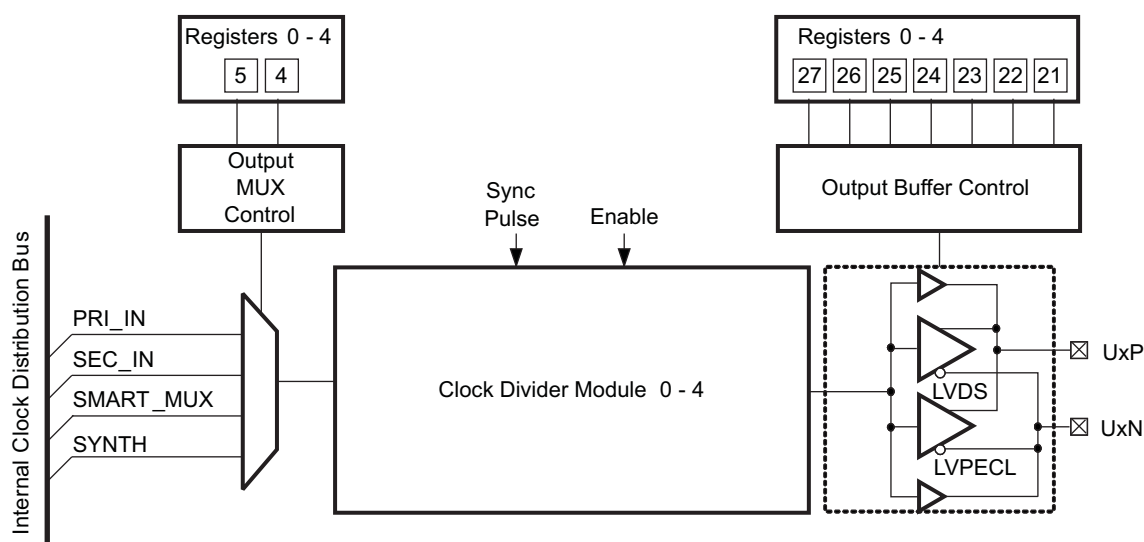


Figure 24. CDCE18005 Output Channel

Output Multiplexer Control

The output multiplexer selects which of the four clock sources available on the Internal Clock Distribution Bus will be presented to the Clock Divider Module. For a description of these clock sources, see [Figure 21](#).

Table 16. CDCE18005 Output Multiplexer Control Settings

OUTPUT MULTIPLEXER CONTROL		CLOCK SOURCE SELECTED
Register n (n = 0,1,2,3,4)		
OUTMUXnSELX n.4	OUTMUXnSELY n.5	
0	0	PRI_IN
0	1	SEC_IN
1	0	AUX_IN
1	1	Reserved

Output Buffer Control

Each of the five output channels includes a programmable output buffer; supporting LVPECL, LVDS, and LVCMOS modes. [Table 17](#) lists the settings required to configure the CDCE18005 for each output type. Registers 0 through 4 correspond to Output Channels 0 through 4 respectively.

Table 17. CDCE18005 Output Buffer Control Settings

OUTPUT BUFFER CONTROL						OUTPUT TYPE
Register n (n = 0,1,2,3,4)						
CMOSMODEnPX	CMOSMODEnPY	CMOSMODEnNX	CMOSMODEnNY	OUTBUFSELnX	OUTBUFSELnY	
n.22	n.23	n.24	n.25	n.26	n.27	
0	0	0	0	0	1	LVPECL
0	1	0	1	1	1	LVDS
See LVCMOS Output Buffer Configuration Settings				0	0	LVCMOS
0	1	0	1	1	0	OFF

Output Buffer Control – LVCMOS Configurations

A LVCMOS output configuration requires additional configuration data. In the single ended configuration, each Output Channel provides a pair of outputs. The CDCE18005 supports four modes of operation for single ended outputs as listed in [Table 18](#).

Table 18. LVCMOS Output Buffer Configuration Settings

OUTPUT BUFFER CONTROL – LVCMOS CONFIGURATION						Output Type	Pin	Output Mode
Register n (n = 0,1,2,3,4)								
CMOSMODEnPX	CMOSMODEnPY	CMOSMODEnNX	CMOSMODEnNY	OUTBUFSELnX	OUTBUFSELnY			
n.22	n.23	n.24	n.25	n.26	n.27			
X	X	0	0	0	0	LVC MOS	Negative	Active – Non-inverted
X	X	0	1	0	0	LVC MOS	Negative	Hi-Z
X	X	1	0	0	0	LVC MOS	Negative	Active – Non-inverted
X	X	1	1	0	0	LVC MOS	Negative	Low
0	0	X	X	0	0	LVC MOS	Positive	Active – Non-inverted
0	1	X	X	0	0	LVC MOS	Positive	Hi-Z
1	0	X	X	0	0	LVC MOS	Positive	Active – Non-inverted
1	1	X	X	0	0	LVC MOS	Positive	Low

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Output Dividers

Figure 25 shows that each output channel provides a 7-bit divider and digital phase adjust block. Table 19 lists the divide ratios supported by the output divider for each output channel. The output divider's maximum input frequency is limited to 1.175GHz. If the divider is bypassed (divide ratio = 1) then the maximum frequency of the output channel is 1.5GHz.

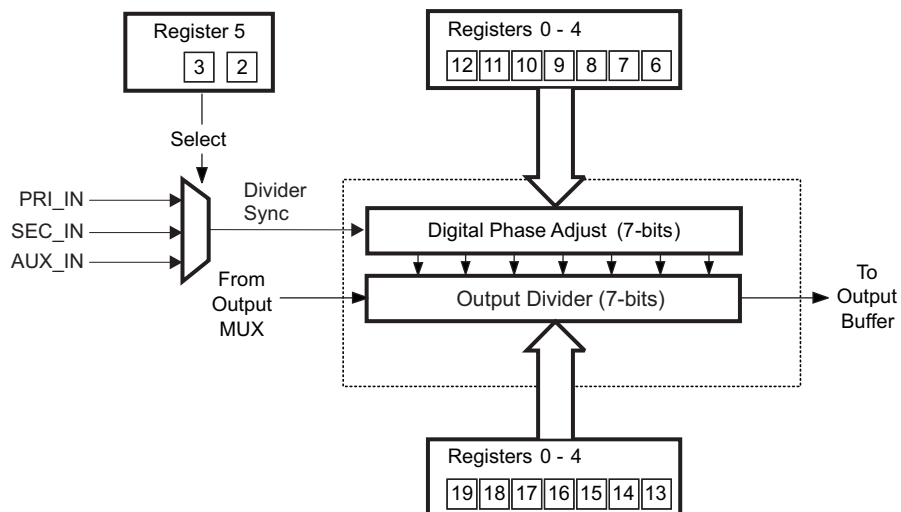


Figure 25. CDCE18005 Output Divider and Phase Adjust

Table19. CDCE18005 Output Divider Settings

OUTPUT DIVIDER n SETTINGS Register n (n = 0,1,2,3,4)						Output Phase*		Output Divide Ratio	
Multiplexer		Integer Divider			Integer Divider Setting				
OUTnDIVSEL6	OUTnDIVSEL5	OUTnDIVSEL4	OUTnDIVSEL3	OUTnDIVSEL2					
n.19	n.18	n.17	n.16	n.15		Cycles	Degree	Output Channels 0-4	Auxiliary Output
X	X	X	X	X		OFF	OFF	OFF	OFF
0	1	0	0	0	–	0	0	1	4
1	0	0	0	0	–	0.5	180	2**	4
1	0	0	0	0	–	0	0	3**	6
1	0	0	0	0	–	0.5	180	4	8
1	0	0	0	0	–	0	0	5	10
0	0	0	0	0	2	21	7560	6	6
0	0	0	0	0	2	28.5	10260	8	8
0	0	0	0	0	2	35	12500	10	10
0	0	0	0	1	4	24	8640	12	12
0	0	0	0	1	4	32.5	11700	16	16
0	0	0	0	1	4	40	14400	20	20
0	0	0	1	0	6	27	9720	18	18
0	0	0	1	0	6	36.5	13140	24	24
0	0	0	1	0	6	45	16200	30	30
0	0	0	1	1	8	40.5	14580	32	32
0	0	0	1	1	8	50	18000	40	40
0	0	1	0	0	10	55	19800	50	50
0	0	1	0	1	12	36	12960	36	36
0	0	1	0	1	12	48.5	17460	48	48
0	0	1	0	1	12	60	21600	60	60
0	0	1	1	0	14	25.5	9540	28	28
0	0	1	1	0	14	39	14040	42	42

CDCE18005

SCAS862, NOVEMBER 2008

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OUTPUT DIVIDER n SETTINGS Register n (n = 0,1,2,3,4)						Output Phase*		Output Divide Ratio	
Multiplexer		Integer Divider			Integer Divider Setting				
OUTnDIVSEL6	OUTnDIVSEL5	OUTnDIVSEL4	OUTnDIVSEL3	OUTnDIVSEL2					
n.19	n.18	n.17	n.16	n.15		Cycles	Degree	Output Channels 0-4	Auxiliary Output
0	0	1	1	0	14	52.5	18900	56	56
0	0	1	1	0	14	65	23400	70	70
0	0	1	1	1	16	56.5	20340	64	64
0	0	1	1	1	16	70	25200	80	80

*These columns show that the output divider generates a unique phase lag in the output clock (relative to the clock from the output multiplexer) determined by the divide ratio used.

**Output channel 2 or 3 determine the auxiliary output divide ratio. For example, if the auxiliary output is programmed to drive via output 2 and output 2 divider is programmed to divide by 3, then the divide ratio for the auxiliary output will be 6.

Digital Phase Adjust

Figure 26 provides an overview of the Digital Phase Adjust feature. The output divider includes a coarse phase adjust that shifts the divided clock signal that drives the output buffer. Essentially, the Digital Phase Adjust timer delays when the output divider starts dividing; thereby shifting the phase of the output clock. The phase adjust resolution is a function of the divide function. Coarse phase adjust parameters include:

- **Number of Phase Delay Steps** – the number of phase delay steps available is equal to the divide ratio selected. For example, if a Divide by 4 is selected, then the Digital Phase Adjust can be programmed to select when the output divider changes state based upon selecting one of the four counts on the input. Figure 26 shows an example of divide by 16 in which there are 16 rising edges of Clock IN at which the output divider changes state (this particular example shows the fourth edge shifting the output by one fourth of the period of the output).
- **Phase Delay Step Size** – the step size is determined by the number of phase delay steps according to the following equations:

$$\text{Stepsize(deg)} = \frac{360 \text{ degrees}}{\text{OutputDivideRatio}} \quad (1)$$

$$\text{Stepsize(sec)} = \frac{1}{f_{\text{ClockIN}} \times \text{OutputDivideRatio}} \quad (2)$$

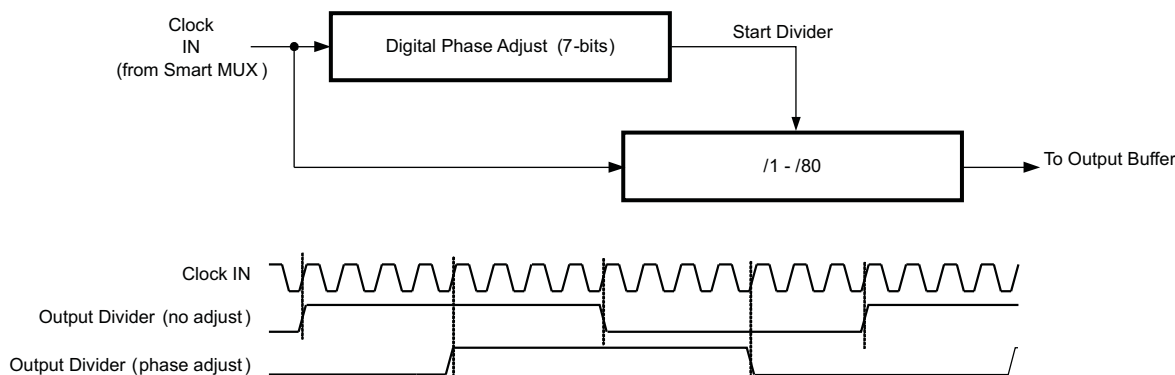


Figure 26. CDCE18005 Phase Adjust

Phase Adjust example

Given:

Output Frequency: 30.72 MHz

Input Frequency: 491.52 MHz

Output Divider Setting: 16

$$\text{Stepsize(deg)} = \frac{360}{32} = 11.25^\circ / \text{Step} \quad (3)$$

The tables that follow provide a list of valid register settings for the digital phase adjust blocks.

Table 20. CDCE18005 Output Coarse Phase Adjust Settings (1)

Divide Ratio	PhnADGC6	PhnADGC5	PhnADGC4	PhnADGC3	PhnADGC2	PhnADGC1	PhnADGC0	Phase Delay
	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
1	0	0	0	0	0	0	0	0
2	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /2)
3	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /3)
	0	0	0	0	0	1	0	2(2 π /3)
4	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /4)
	0	0	0	0	0	1	0	2(2 π /4)
	0	0	0	0	0	1	1	3(2 π /4)
5	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /5)
	0	0	0	0	0	1	0	2(2 π /5)
	0	0	0	0	0	1	1	3(2 π /5)
	0	0	0	0	1	0	0	4(2 π /5)
6	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /6)
	0	0	0	0	0	1	0	2(2 π /6)
	1	0	0	0	0	0	0	3(2 π /6)
	1	0	0	0	0	0	1	4(2 π /6)
	1	0	0	0	0	1	0	5(2 π /6)
8	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /8)
	0	0	0	0	0	1	0	2(2 π /8)
	0	0	0	0	0	1	1	3(2 π /8)
	1	0	0	0	0	0	0	4(2 π /8)
	1	0	0	0	0	0	1	5(2 π /8)
	1	0	0	0	0	1	0	6(2 π /8)
	1	0	0	0	0	1	1	7(2 π /8)
10	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /10)
	0	0	0	0	0	1	0	2(2 π /10)
	0	0	0	0	0	1	1	3(2 π /10)
	0	0	0	0	1	0	0	4(2 π /10)
	1	0	0	0	0	0	0	5(2 π /10)
	1	0	0	0	0	0	1	6(2 π /10)
	1	0	0	0	0	1	0	7(2 π /10)
	1	0	0	0	0	1	1	8(2 π /10)
	1	0	0	0	1	0	0	9(2 π /10)
12	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /12)
	0	0	0	0	0	1	0	2(2 π /12)
	0	0	0	1	0	0	0	3(2 π /12)
	0	0	0	1	0	0	1	4(2 π /12)
	0	0	0	1	0	1	0	5(2 π /12)
	0	0	1	0	0	0	0	6(2 π /12)
	0	0	1	0	0	0	1	7(2 π /12)
	0	0	1	0	0	1	0	8(2 π /12)
	0	0	1	1	0	0	0	9(2 π /12)
	0	0	1	1	0	0	1	10(2 π /12)
	0	0	1	1	0	1	0	11(2 π /12)
16	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /16)
	0	0	0	0	0	1	0	2(2 π /16)
	0	0	0	0	0	1	1	3(2 π /16)
	0	0	0	1	0	0	0	4(2 π /16)
	0	0	0	1	0	0	1	5(2 π /16)
	0	0	0	1	0	1	0	6(2 π /16)
	0	0	0	1	0	1	1	7(2 π /16)
	0	0	1	0	0	0	0	8(2 π /16)
	0	0	1	0	0	0	1	9(2 π /16)
	0	0	1	0	0	1	0	10(2 π /16)
	0	0	1	0	0	1	1	11(2 π /16)
	0	0	1	1	0	0	0	12(2 π /16)
	0	0	1	1	0	0	1	13(2 π /16)
	0	0	1	1	0	1	0	14(2 π /16)
	0	0	1	1	0	1	1	15(2 π /16)

Divide Ratio	PhnADGC6	PhnADGC5	PhnADGC4	PhnADGC3	PhnADGC2	PhnADGC1	PhnADGC0	Phase Delay
	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
18	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /18)
	0	0	0	0	0	1	0	2(2 π /18)
	0	0	0	1	0	0	0	3(2 π /18)
	0	0	0	1	0	0	1	4(2 π /18)
	0	0	0	1	0	1	0	5(2 π /18)
	0	0	1	0	0	0	0	6(2 π /18)
	0	0	1	0	0	0	1	7(2 π /18)
	0	0	1	0	0	1	0	8(2 π /18)
	0	0	1	1	0	0	0	9(2 π /18)
	0	0	1	1	0	0	1	10(2 π /18)
	0	0	1	1	0	1	0	11(2 π /18)
	0	1	0	0	0	0	0	12(2 π /18)
	0	1	0	0	0	0	1	13(2 π /18)
	0	1	0	0	0	1	0	14(2 π /18)
	0	1	0	1	0	0	0	15(2 π /18)
	0	1	0	1	0	0	1	16(2 π /18)
	0	1	0	1	0	1	0	17(2 π /18)
20	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /20)
	0	0	0	0	0	1	0	2(2 π /20)
	0	0	0	0	0	1	1	3(2 π /20)
	0	0	0	0	1	0	0	4(2 π /20)
	0	0	0	1	0	0	0	5(2 π /20)
	0	0	0	1	0	0	1	6(2 π /20)
	0	0	0	1	0	1	0	7(2 π /20)
	0	0	0	1	0	1	1	8(2 π /20)
	0	0	0	1	1	0	0	9(2 π /20)
	0	0	1	0	0	0	0	10(2 π /20)
	0	0	1	0	0	0	1	11(2 π /20)
	0	0	1	0	0	1	0	12(2 π /20)
	0	0	1	0	0	1	1	13(2 π /20)
	0	0	1	0	1	0	0	14(2 π /20)
	0	0	1	1	0	0	0	15(2 π /20)
	0	0	1	1	0	0	1	16(2 π /20)
	0	0	1	1	0	1	0	17(2 π /20)
	0	0	1	1	0	1	1	18(2 π /20)
	0	0	1	1	1	0	0	19(2 π /20)
24	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /24)
	0	0	0	0	0	1	0	2(2 π /24)
	0	0	0	0	0	1	1	3(2 π /24)
	0	0	0	1	0	0	0	4(2 π /24)
	0	0	0	1	0	0	1	5(2 π /24)
	0	0	0	1	0	1	0	6(2 π /24)
	0	0	0	1	0	1	1	7(2 π /24)
	0	0	1	0	0	0	0	8(2 π /24)
	0	0	1	0	0	0	1	9(2 π /24)
	0	0	1	0	0	1	0	10(2 π /24)
	0	0	1	0	0	1	1	11(2 π /24)
	0	0	1	1	0	0	0	12(2 π /24)
	0	0	1	1	0	0	1	13(2 π /24)
	0	0	1	1	0	1	0	14(2 π /24)
	0	0	1	1	0	1	1	15(2 π /24)
	0	1	0	0	0	0	0	16(2 π /24)
	0	1	0	0	0	0	1	17(2 π /24)
	0	1	0	0	0	1	0	18(2 π /24)
	0	1	0	0	0	1	1	19(2 π /24)
	0	1	0	1	0	0	0	20(2 π /24)
	0	1	0	1	0	0	1	21(2 π /24)
	0	1	0	1	0	1	0	22(2 π /24)
	0	1	0	1	0	1	1	23(2 π /24)

Table 21. CDCE18005 Output Coarse Phase Adjust Settings (2)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay (radian)
28	n.12	n.11	n.10	n.9	n.8	n.7	n.6	
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /28)
	0	0	0	1	0	0	0	2(2 π /28)
	0	0	0	1	0	0	1	3(2 π /28)
	0	0	1	0	0	0	0	4(2 π /28)
	0	0	1	0	0	0	1	5(2 π /28)
	0	0	1	1	0	0	0	6(2 π /28)
	0	0	1	1	0	0	1	7(2 π /28)
	0	1	0	0	0	0	0	8(2 π /28)
	0	1	0	0	0	0	1	9(2 π /28)
	0	1	0	1	0	0	0	10(2 π /28)
	0	1	0	1	0	0	1	11(2 π /28)
	0	1	1	0	0	0	0	12(2 π /28)
	0	1	1	0	0	0	1	13(2 π /28)
	1	0	0	0	0	0	0	14(2 π /28)
	1	0	0	0	0	0	1	15(2 π /28)
	1	0	0	1	0	0	0	16(2 π /28)
	1	0	0	1	0	0	1	17(2 π /28)
	1	0	1	0	0	0	0	18(2 π /28)
	1	0	1	0	0	0	1	19(2 π /28)
	1	0	1	1	0	0	0	20(2 π /28)
	1	0	1	1	0	0	1	21(2 π /28)
	1	1	0	0	0	0	0	22(2 π /28)
	1	1	0	0	0	0	1	23(2 π /28)
	1	1	0	1	0	0	0	24(2 π /28)
	1	1	0	1	0	0	1	25(2 π /28)
	1	1	1	0	0	0	0	26(2 π /28)
	1	1	1	0	0	0	1	27(2 π /28)
30								
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /30)
	0	0	0	0	0	1	0	2(2 π /30)
	0	0	0	0	0	1	1	3(2 π /30)
	0	0	0	0	1	0	0	4(2 π /30)
	0	0	0	1	0	0	0	5(2 π /30)
	0	0	0	1	0	0	1	6(2 π /30)
	0	0	0	1	0	1	0	7(2 π /30)
	0	0	0	1	0	1	1	8(2 π /30)
	0	0	0	1	1	0	0	9(2 π /30)
	0	0	1	0	0	0	0	10(2 π /30)
	0	0	1	0	0	0	1	11(2 π /30)
	0	0	1	0	0	1	0	12(2 π /30)
	0	0	1	0	0	1	1	13(2 π /30)
	0	0	1	0	1	0	0	14(2 π /30)
	0	0	1	1	0	0	0	15(2 π /30)
	0	0	1	1	0	0	1	16(2 π /30)
	0	0	1	1	0	1	0	17(2 π /30)
	0	0	1	1	0	1	1	18(2 π /30)
	0	0	1	1	1	0	0	19(2 π /30)
	0	1	0	0	0	0	0	20(2 π /30)
	0	1	0	0	0	0	1	21(2 π /30)
	0	1	0	0	0	1	0	22(2 π /30)
	0	1	0	0	0	1	1	23(2 π /30)
	0	1	0	0	1	0	0	24(2 π /30)
	0	1	0	1	0	0	0	25(2 π /30)
	0	1	0	1	0	0	1	26(2 π /30)
	0	1	0	1	0	1	0	27(2 π /30)
	0	1	0	1	0	1	1	28(2 π /30)
	0	1	0	1	1	0	0	29(2 π /30)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay (radian)
32	n.12	n.11	n.10	n.9	n.8	n.7	n.6	
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /32)
	0	0	0	0	0	1	0	2(2 π /32)
	0	0	0	0	0	1	1	3(2 π /32)
	0	0	0	1	0	0	0	4(2 π /32)
	0	0	0	1	0	0	1	5(2 π /32)
	0	0	0	1	0	1	0	6(2 π /32)
	0	0	0	1	0	1	1	7(2 π /32)
	0	0	1	0	0	0	0	8(2 π /32)
	0	0	1	0	0	0	1	9(2 π /32)
	0	0	1	0	0	1	0	10(2 π /32)
	0	0	1	0	0	1	1	11(2 π /32)
	0	0	1	1	0	0	0	12(2 π /32)
	0	0	1	1	0	0	1	13(2 π /32)
	0	0	1	1	0	1	0	14(2 π /32)
	0	0	1	1	0	1	1	15(2 π /32)
	0	1	0	0	0	0	0	16(2 π /32)
	0	1	0	0	0	0	1	17(2 π /32)
	0	1	0	0	0	1	0	18(2 π /32)
	0	1	0	0	0	1	1	19(2 π /32)
	0	1	0	1	0	0	0	20(2 π /32)
	0	1	0	1	0	0	1	21(2 π /32)
	0	1	0	1	0	1	0	22(2 π /32)
	0	1	0	1	0	1	1	23(2 π /32)
	0	1	1	0	0	0	0	24(2 π /32)
	0	1	1	0	0	0	1	25(2 π /32)
	0	1	1	0	0	1	0	26(2 π /32)
	0	1	1	0	0	1	1	27(2 π /32)
	0	1	1	1	0	0	0	28(2 π /32)
	0	1	1	1	0	0	1	29(2 π /32)
	0	1	1	1	0	1	0	30(2 π /32)
	0	1	1	1	0	1	1	31(2 π /32)
36								
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /36)
	0	0	0	0	0	1	0	2(2 π /36)
	0	0	0	1	0	0	0	3(2 π /36)
	0	0	0	1	0	0	1	4(2 π /36)
	0	0	0	1	0	1	0	5(2 π /36)
	0	0	1	0	0	0	0	6(2 π /36)
	0	0	1	0	0	0	1	7(2 π /36)
	0	0	1	0	0	1	0	8(2 π /36)
	0	0	1	1	0	0	0	9(2 π /36)
	0	0	1	1	0	0	1	10(2 π /36)
	0	0	1	1	0	1	0	11(2 π /36)
	0	1	0	0	0	0	0	12(2 π /36)
	0	1	0	0	0	0	1	13(2 π /36)
	0	1	0	0	0	1	0	14(2 π /36)
	0	1	0	1	0	0	0	15(2 π /36)
	0	1	0	1	0	0	1	16(2 π /36)
	0	1	0	1	0	1	0	17(2 π /36)
	1	0	0	0	0	0	0	18(2 π /36)
	1	0	0	0	0	0	1	19(2 π /36)
	1	0	0	0	0	1	0	20(2 π /36)
	1	0	0	1	0	0	0	21(2 π /36)
	1	0	0	1	0	0	1	22(2 π /36)
	1	0	0	1	0	1	0	23(2 π /36)
	1	0	1	0	0	0	0	24(2 π /36)
	1	0	1	0	0	0	1	25(2 π /36)
	1	0	1	0	0	1	0	26(2 π /36)
	1	0	1	1	0	0	0	27(2 π /36)
	1	0	1	1	0	0	1	28(2 π /36)
	1	0	1	1	0	1	0	29(2 π /36)
	1	1	0	0	0	0	0	30(2 π /36)
	1	1	0	0	0	0	1	31(2 π /36)
	1	1	0	0	0	1	0	32(2 π /36)
	1	1	0	1	0	0	0	33(2 π /36)
	1	1	0	1	0	0	1	34(2 π /36)
	1	1	0	1	0	1	0	35(2 π /36)

Table 22. CDCE18005 Output Coarse Phase Adjust Settings (3)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay (radian)
40	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /40)
	0	0	0	0	0	1	0	2(2 π /40)
	0	0	0	0	0	1	1	3(2 π /40)
	0	0	0	0	1	0	0	4(2 π /40)
	0	0	0	1	0	0	0	5(2 π /40)
	0	0	0	1	0	0	1	6(2 π /40)
	0	0	0	1	0	1	0	7(2 π /40)
	0	0	0	1	0	1	1	8(2 π /40)
	0	0	0	1	1	0	0	9(2 π /40)
	0	0	1	0	0	0	0	10(2 π /40)
	0	0	1	0	0	0	1	11(2 π /40)
	0	0	1	0	0	1	0	12(2 π /40)
	0	0	1	0	0	1	1	13(2 π /40)
	0	0	1	0	1	0	0	14(2 π /40)
	0	0	1	1	0	0	0	15(2 π /40)
	0	0	1	1	0	0	1	16(2 π /40)
	0	0	1	1	0	1	0	17(2 π /40)
	0	0	1	1	0	1	1	18(2 π /40)
	0	0	1	1	1	0	0	19(2 π /40)
	0	1	0	0	0	0	0	20(2 π /40)
	0	1	0	0	0	0	1	21(2 π /40)
	0	1	0	0	0	1	0	22(2 π /40)
	0	1	0	0	0	1	1	23(2 π /40)
	0	1	0	0	1	0	0	24(2 π /40)
	0	1	0	1	0	0	0	25(2 π /40)
	0	1	0	1	0	0	1	26(2 π /40)
	0	1	0	1	0	1	0	27(2 π /40)
	0	1	0	1	0	1	1	28(2 π /40)
	0	1	0	1	1	0	0	29(2 π /40)
	0	1	1	0	0	0	0	30(2 π /40)
	0	1	1	0	0	0	1	31(2 π /40)
	0	1	1	0	0	1	0	32(2 π /40)
	0	1	1	0	0	1	1	33(2 π /40)
	0	1	1	0	1	0	0	34(2 π /40)
	0	1	1	1	0	0	0	35(2 π /40)
	0	1	1	1	0	0	1	36(2 π /40)
	0	1	1	1	0	1	0	37(2 π /40)
	0	1	1	1	1	0	1	38(2 π /40)
	0	1	1	1	1	0	0	39(2 π /40)
42	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /42)
	0	0	0	0	0	1	0	2(2 π /42)
	0	0	0	1	0	0	0	3(2 π /42)
	0	0	0	1	0	0	1	4(2 π /42)
	0	0	0	1	0	1	0	5(2 π /42)
	0	0	1	0	0	0	0	6(2 π /42)
	0	0	1	0	0	0	1	7(2 π /42)
	0	0	1	0	0	1	0	8(2 π /42)
	0	0	1	1	0	0	0	9(2 π /42)
	0	0	1	1	0	0	1	10(2 π /42)
	0	0	1	1	0	1	0	11(2 π /42)
	0	1	0	0	0	0	0	12(2 π /42)
	0	1	0	0	0	0	1	13(2 π /42)
	0	1	0	0	0	1	0	14(2 π /42)
	0	1	0	1	0	0	0	15(2 π /42)
	0	1	0	1	0	0	1	16(2 π /42)
	0	1	0	1	0	1	0	17(2 π /42)
	0	1	1	0	0	0	0	18(2 π /42)
	0	1	1	0	0	0	1	19(2 π /42)
	0	1	1	0	0	1	0	20(2 π /42)
	1	0	0	0	0	0	0	21(2 π /42)
	1	0	0	0	0	0	1	22(2 π /42)
	1	0	0	0	0	1	0	23(2 π /42)
	1	0	0	1	0	0	0	24(2 π /42)
	1	0	0	1	0	0	1	25(2 π /42)
	1	0	0	1	0	1	0	26(2 π /42)
	1	0	1	0	0	0	0	27(2 π /42)
	1	0	1	0	0	0	1	28(2 π /42)
	1	0	1	0	0	1	0	29(2 π /42)
	1	0	1	1	0	0	0	30(2 π /42)
	1	0	1	1	0	0	1	31(2 π /42)
	1	0	1	1	0	1	0	32(2 π /42)
	1	1	0	0	0	0	0	33(2 π /42)
	1	1	0	0	0	0	1	34(2 π /42)
	1	1	0	0	0	1	0	35(2 π /42)
	1	1	0	1	0	0	0	36(2 π /42)
	1	1	0	1	0	0	1	37(2 π /42)
	1	1	0	1	0	1	0	38(2 π /42)
	1	1	1	0	0	0	0	39(2 π /42)
	1	1	1	0	0	0	1	40(2 π /42)
	1	1	1	0	0	1	0	41(2 π /42)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay (radian)
48	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /48)
	0	0	0	0	0	1	0	2(2 π /48)
	0	0	0	0	0	1	1	3(2 π /48)
	0	0	0	1	0	0	0	4(2 π /48)
	0	0	0	1	0	0	1	5(2 π /48)
	0	0	0	1	0	1	0	6(2 π /48)
	0	0	0	1	0	1	1	7(2 π /48)
	0	0	1	0	0	0	0	8(2 π /48)
	0	0	1	0	0	0	1	9(2 π /48)
	0	0	1	0	0	1	0	10(2 π /48)
	0	0	1	0	0	1	1	11(2 π /48)
	0	0	1	1	0	0	0	12(2 π /48)
	0	0	1	1	0	0	1	13(2 π /48)
	0	0	1	1	0	1	0	14(2 π /48)
	0	0	1	1	0	1	1	15(2 π /48)
	0	1	0	0	0	0	0	16(2 π /48)
	0	1	0	0	0	0	1	17(2 π /48)
	0	1	0	0	0	1	0	18(2 π /48)
	0	1	0	0	0	1	1	19(2 π /48)
	0	1	0	1	0	0	0	20(2 π /48)
	0	1	0	1	0	0	1	21(2 π /48)
	0	1	0	1	0	1	0	22(2 π /48)
	0	1	0	1	0	1	1	23(2 π /48)
	1	0	0	0	0	0	0	24(2 π /48)
	1	0	0	0	0	0	1	25(2 π /48)
	1	0	0	0	0	1	0	26(2 π /48)
	1	0	0	0	0	1	1	27(2 π /48)
	1	0	0	1	0	0	0	28(2 π /48)
	1	0	0	1	0	0	1	29(2 π /48)
	1	0	0	1	0	1	0	30(2 π /48)
	1	0	0	1	0	1	1	31(2 π /48)
	1	0	1	0	0	0	0	32(2 π /48)
	1	0	1	0	0	0	1	33(2 π /48)
	1	0	1	0	0	1	0	34(2 π /48)
	1	0	1	0	0	1	1	35(2 π /48)
	1	0	1	1	0	0	0	36(2 π /48)
	1	0	1	1	0	0	1	37(2 π /48)
	1	0	1	1	0	1	0	38(2 π /48)
	1	0	1	1	0	1	1	39(2 π /48)
	1	1	0	0	0	0	0	40(2 π /48)
	1	1	0	0	0	0	1	41(2 π /48)
	1	1	0	0	0	1	0	42(2 π /48)
	1	1	0	0	0	1	1	43(2 π /48)
	1	1	0	1	0	0	0	44(2 π /48)
	1	1	0	1	0	0	1	45(2 π /48)
	1	1	0	1	0	1	0	46(2 π /48)
	1	1	0	1	0	1	1	47(2 π /48)

Table 23. CDCE18005 Output Coarse Phase Adjust Settings (4)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay
	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
50	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /50)
	0	0	0	0	0	1	0	2(2 π /50)
	0	0	0	0	0	1	1	3(2 π /50)
	0	0	0	0	1	0	0	4(2 π /50)
	0	0	0	1	0	0	0	5(2 π /50)
	0	0	0	1	0	0	1	6(2 π /50)
	0	0	0	1	0	1	0	7(2 π /50)
	0	0	0	1	0	1	1	8(2 π /50)
	0	0	0	1	1	0	0	9(2 π /50)
	0	0	1	0	0	0	0	10(2 π /50)
	0	0	1	0	0	0	1	11(2 π /50)
	0	0	1	0	0	1	0	12(2 π /50)
	0	0	1	0	0	1	1	13(2 π /50)
	0	0	1	0	1	0	0	14(2 π /50)
	0	0	1	1	0	0	0	15(2 π /50)
	0	0	1	1	0	0	1	16(2 π /50)
	0	0	1	1	0	1	0	17(2 π /50)
	0	0	1	1	0	1	1	18(2 π /50)
	0	0	1	1	1	0	0	19(2 π /50)
	0	1	0	0	0	0	0	20(2 π /50)
	0	1	0	0	0	0	1	21(2 π /50)
	0	1	0	0	0	1	0	22(2 π /50)
	0	1	0	0	0	1	1	23(2 π /50)
	0	1	0	0	1	0	0	24(2 π /50)
	1	0	0	0	0	0	0	25(2 π /50)
	1	0	0	0	0	0	1	26(2 π /50)
	1	0	0	0	0	1	0	27(2 π /50)
	1	0	0	0	0	1	1	28(2 π /50)
	1	0	0	0	1	0	0	29(2 π /50)
	1	0	0	1	0	0	0	30(2 π /50)
	1	0	0	1	0	0	1	31(2 π /50)
	1	0	0	1	0	1	0	32(2 π /50)
	1	0	0	1	0	1	1	33(2 π /50)
	1	0	0	1	1	0	0	34(2 π /50)
	1	0	1	0	0	0	0	35(2 π /50)
	1	0	1	0	0	0	1	36(2 π /50)
	1	0	1	0	0	1	0	37(2 π /50)
	1	0	1	0	0	1	1	38(2 π /50)
	1	0	1	0	1	0	0	39(2 π /50)
	1	0	1	1	0	0	0	40(2 π /50)
	1	0	1	1	0	0	1	41(2 π /50)
	1	0	1	1	0	1	0	42(2 π /50)
	1	0	1	1	0	1	1	43(2 π /50)
	1	0	1	1	1	0	0	44(2 π /50)
	1	1	0	0	0	0	0	45(2 π /50)
	1	1	0	0	0	0	1	46(2 π /50)
	1	1	0	0	0	1	0	47(2 π /50)
	1	1	0	0	0	1	1	48(2 π /50)
	1	1	0	0	1	0	0	49(2 π /50)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay
	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
56	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /56)
	0	0	0	0	0	1	0	2(2 π /56)
	0	0	0	0	0	1	1	3(2 π /56)
	0	0	0	1	0	0	0	4(2 π /56)
	0	0	0	1	0	0	1	5(2 π /56)
	0	0	0	1	0	1	0	6(2 π /56)
	0	0	0	1	0	1	1	7(2 π /56)
	0	0	1	0	0	0	0	8(2 π /56)
	0	0	1	0	0	0	1	9(2 π /56)
	0	0	1	0	0	1	0	10(2 π /56)
	0	0	1	0	0	1	1	11(2 π /56)
	0	0	1	1	0	0	0	12(2 π /56)
	0	0	1	1	0	0	1	13(2 π /56)
	0	0	1	1	0	1	0	14(2 π /56)
	0	0	1	1	0	1	1	15(2 π /56)
	0	1	0	0	0	0	0	16(2 π /56)
	0	1	0	0	0	0	1	17(2 π /56)
	0	1	0	0	0	1	0	18(2 π /56)
	0	1	0	0	0	1	1	19(2 π /56)
	0	1	0	1	0	0	0	20(2 π /56)
	0	1	0	1	0	0	1	21(2 π /56)
	0	1	0	1	0	1	0	22(2 π /56)
	0	1	0	1	0	1	1	23(2 π /56)
	0	1	1	0	0	0	0	24(2 π /56)
	0	1	1	0	0	0	1	25(2 π /56)
	0	1	1	0	0	1	0	26(2 π /56)
	0	1	1	0	0	1	1	27(2 π /56)
	1	0	0	0	0	0	0	28(2 π /56)
	1	0	0	0	0	0	1	29(2 π /56)
	1	0	0	0	0	1	0	30(2 π /56)
	1	0	0	0	0	1	1	31(2 π /56)
	1	0	0	1	0	0	0	32(2 π /56)
	1	0	0	1	0	0	1	33(2 π /56)
	1	0	0	1	0	1	0	34(2 π /56)
	1	0	0	1	0	1	1	35(2 π /56)
	1	0	1	0	0	0	0	36(2 π /56)
	1	0	1	0	0	0	1	37(2 π /56)
	1	0	1	0	0	1	0	38(2 π /56)
	1	0	1	0	0	1	1	39(2 π /56)
	1	0	1	1	0	0	0	40(2 π /56)
	1	0	1	1	0	0	1	41(2 π /56)
	1	0	1	1	0	1	0	42(2 π /56)
	1	0	1	1	0	1	1	43(2 π /56)
	1	1	0	0	0	0	0	44(2 π /56)
	1	1	0	0	0	0	1	45(2 π /56)
	1	1	0	0	0	1	0	46(2 π /56)
	1	1	0	0	0	1	1	47(2 π /56)
	1	1	0	1	0	0	0	48(2 π /56)
	1	1	0	1	0	0	1	49(2 π /56)
	1	1	0	1	0	1	0	50(2 π /56)
	1	1	0	1	0	1	1	51(2 π /56)
	1	1	1	0	0	0	0	52(2 π /56)
	1	1	1	0	0	0	1	53(2 π /56)
	1	1	1	0	0	1	0	54(2 π /56)
	1	1	1	0	0	1	1	55(2 π /56)

Table 24. CDCE18005 Output Coarse Phase Adjust Settings (5)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay
	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
60	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /60)
	0	0	0	0	0	1	0	2(2 π /60)
	0	0	0	0	0	1	1	3(2 π /60)
	0	0	0	0	1	0	0	4(2 π /60)
	0	0	0	1	0	0	0	5(2 π /60)
	0	0	0	1	0	0	1	6(2 π /60)
	0	0	0	1	0	1	0	7(2 π /60)
	0	0	0	1	0	1	1	8(2 π /60)
	0	0	0	1	1	0	0	9(2 π /60)
	0	0	1	0	0	0	0	10(2 π /60)
	0	0	1	0	0	0	1	11(2 π /60)
	0	0	1	0	0	1	0	12(2 π /60)
	0	0	1	0	0	1	1	13(2 π /60)
	0	0	1	0	1	0	0	14(2 π /60)
	0	0	1	1	0	0	0	15(2 π /60)
	0	0	1	1	0	0	1	16(2 π /60)
	0	0	1	1	0	1	0	17(2 π /60)
	0	0	1	1	0	1	1	18(2 π /60)
	0	0	1	1	1	0	0	19(2 π /60)
	0	1	0	0	0	0	0	20(2 π /60)
	0	1	0	0	0	0	1	21(2 π /60)
	0	1	0	0	0	1	0	22(2 π /60)
	0	1	0	0	0	1	1	23(2 π /60)
	0	1	0	0	1	0	0	24(2 π /60)
	0	1	0	1	0	0	0	25(2 π /60)
	0	1	0	1	0	0	1	26(2 π /60)
	0	1	0	1	0	1	0	27(2 π /60)
	0	1	0	1	0	1	1	28(2 π /60)
	0	1	0	1	1	0	0	29(2 π /60)
	1	0	0	0	0	0	0	30(2 π /60)
	1	0	0	0	0	0	1	31(2 π /60)
	1	0	0	0	0	1	0	32(2 π /60)
	1	0	0	0	0	1	1	33(2 π /60)
	1	0	0	0	1	0	0	34(2 π /60)
	1	0	0	1	0	0	0	35(2 π /60)
	1	0	0	1	0	0	1	36(2 π /60)
	1	0	0	1	0	1	0	37(2 π /60)
	1	0	0	1	0	1	1	38(2 π /60)
	1	0	0	1	1	0	0	39(2 π /60)
	1	0	1	0	0	0	0	40(2 π /60)
	1	0	1	0	0	0	1	41(2 π /60)
	1	0	1	0	0	1	0	42(2 π /60)
	1	0	1	0	0	1	1	43(2 π /60)
	1	0	1	0	1	0	0	44(2 π /60)
	1	0	1	1	0	0	0	45(2 π /60)
	1	0	1	1	0	0	1	46(2 π /60)
	1	0	1	1	0	1	0	47(2 π /60)
	1	0	1	1	0	1	1	48(2 π /60)
	1	0	1	1	1	0	0	49(2 π /60)
	1	1	0	0	0	0	0	50(2 π /60)
	1	1	0	0	0	0	1	51(2 π /60)
	1	1	0	0	0	1	0	52(2 π /60)
	1	1	0	0	0	1	1	53(2 π /60)
	1	1	0	0	1	0	0	54(2 π /60)
	1	1	0	1	0	0	0	55(2 π /60)
	1	1	0	1	0	0	1	56(2 π /60)
	1	1	0	1	0	1	0	57(2 π /60)
	1	1	0	1	0	1	1	58(2 π /60)
	1	1	0	1	1	0	0	59(2 π /60)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay
	n.12	n.11	n.10	n.9	n.8	n.7	n.6	(radian)
64	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /64)
	0	0	0	0	0	1	0	2(2 π /64)
	0	0	0	0	0	1	1	3(2 π /64)
	0	0	0	1	0	0	0	4(2 π /64)
	0	0	0	1	0	0	1	5(2 π /64)
	0	0	0	1	0	1	0	6(2 π /64)
	0	0	0	1	0	1	1	7(2 π /64)
	0	0	1	0	0	0	0	8(2 π /64)
	0	0	1	0	0	0	1	9(2 π /64)
	0	0	1	0	0	1	0	10(2 π /64)
	0	0	1	0	0	1	1	11(2 π /64)
	0	0	1	1	0	0	0	12(2 π /64)
	0	0	1	1	0	0	1	13(2 π /64)
	0	0	1	1	0	1	0	14(2 π /64)
	0	0	1	1	0	1	1	15(2 π /64)
	0	1	0	0	0	0	0	16(2 π /64)
	0	1	0	0	0	0	1	17(2 π /64)
	0	1	0	0	0	1	0	18(2 π /64)
	0	1	0	0	0	1	1	19(2 π /64)
	0	1	0	1	0	0	0	20(2 π /64)
	0	1	0	1	0	0	1	21(2 π /64)
	0	1	0	1	0	1	0	22(2 π /64)
	0	1	0	1	0	1	1	23(2 π /64)
	0	1	1	0	0	0	0	24(2 π /64)
	0	1	1	0	0	0	1	25(2 π /64)
	0	1	1	0	0	1	0	26(2 π /64)
	0	1	1	0	0	1	1	27(2 π /64)
	0	1	1	1	0	0	0	28(2 π /64)
	0	1	1	1	0	0	1	29(2 π /64)
	0	1	1	1	0	1	0	30(2 π /64)
	0	1	1	1	0	1	1	31(2 π /64)
	1	0	0	0	0	0	0	32(2 π /64)
	1	0	0	0	0	0	1	33(2 π /64)
	1	0	0	0	0	1	0	34(2 π /64)
	1	0	0	0	0	1	1	35(2 π /64)
	1	0	0	1	0	0	0	36(2 π /64)
	1	0	0	1	0	0	1	37(2 π /64)
	1	0	0	1	0	1	0	38(2 π /64)
	1	0	0	1	0	1	1	39(2 π /64)
	1	0	1	0	0	0	0	40(2 π /64)
	1	0	1	0	0	0	1	41(2 π /64)
	1	0	1	0	0	1	0	42(2 π /64)
	1	0	1	0	0	1	1	43(2 π /64)
	1	0	1	1	0	0	0	44(2 π /64)
	1	0	1	1	0	0	1	45(2 π /64)
	1	0	1	1	0	1	0	46(2 π /64)
	1	0	1	1	0	1	1	47(2 π /64)
	1	1	0	0	0	0	0	48(2 π /64)
	1	1	0	0	0	0	1	49(2 π /64)
	1	1	0	0	0	1	0	50(2 π /64)
	1	1	0	0	0	1	1	51(2 π /64)
	1	1	0	1	0	0	0	52(2 π /64)
	1	1	0	1	0	0	1	53(2 π /64)
	1	1	0	1	0	1	0	54(2 π /64)
	1	1	0	1	0	1	1	55(2 π /64)
	1	1	1	0	0	0	0	56(2 π /64)
	1	1	1	0	0	0	1	57(2 π /64)
	1	1	1	0	0	1	0	58(2 π /64)
	1	1	1	0	0	1	1	59(2 π /64)
	1	1	1	1	0	0	0	60(2 π /64)
	1	1	1	1	0	0	1	61(2 π /64)
	1	1	1	1	0	1	0	62(2 π /64)
	1	1	1	1	0	1	1	63(2 π /64)

Table 25. CDCE18005 Output Coarse Phase Adjust Settings (6)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay (radian)
n.12	n.11	n.10	n.9	n.8	n.7	n.6		
70	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /70)
	0	0	0	0	0	1	0	2(2 π /70)
	0	0	0	0	0	1	1	3(2 π /70)
	0	0	0	0	1	0	0	4(2 π /70)
	0	0	0	1	0	0	0	5(2 π /70)
	0	0	0	1	0	0	1	6(2 π /70)
	0	0	0	1	0	1	0	7(2 π /70)
	0	0	0	1	0	1	1	8(2 π /70)
	0	0	0	1	1	0	0	9(2 π /70)
	0	0	1	0	0	0	0	10(2 π /70)
	0	0	1	0	0	0	1	11(2 π /70)
	0	0	1	0	0	1	0	12(2 π /70)
	0	0	1	0	0	1	1	13(2 π /70)
	0	0	1	0	1	0	0	14(2 π /70)
	0	0	1	1	0	0	0	15(2 π /70)
	0	0	1	1	0	0	1	16(2 π /70)
	0	0	1	1	0	1	0	17(2 π /70)
	0	0	1	1	0	1	1	18(2 π /70)
	0	0	1	1	1	0	0	19(2 π /70)
	0	1	0	0	0	0	0	20(2 π /70)
	0	1	0	0	0	0	1	21(2 π /70)
	0	1	0	0	0	1	0	22(2 π /70)
	0	1	0	0	0	1	1	23(2 π /70)
	0	1	0	0	1	0	0	24(2 π /70)
	0	1	0	1	0	0	0	25(2 π /70)
	0	1	0	1	0	0	1	26(2 π /70)
	0	1	0	1	0	1	0	27(2 π /70)
	0	1	0	1	0	1	1	28(2 π /70)
	0	1	0	1	1	0	0	29(2 π /70)
	0	1	1	0	0	0	0	30(2 π /70)
	0	1	1	0	0	0	1	31(2 π /70)
	0	1	1	0	0	1	0	32(2 π /70)
	0	1	1	0	0	1	1	33(2 π /70)
	0	1	1	0	1	0	0	34(2 π /70)
	1	0	0	0	0	0	0	35(2 π /70)
	1	0	0	0	0	0	1	36(2 π /70)
	1	0	0	0	0	1	0	37(2 π /70)
	1	0	0	0	0	1	1	38(2 π /70)
	1	0	0	0	1	0	0	39(2 π /70)
	1	0	0	1	0	0	0	40(2 π /70)
	1	0	0	1	0	0	1	41(2 π /70)
	1	0	0	1	0	1	0	42(2 π /70)
	1	0	0	1	0	1	1	43(2 π /70)
	1	0	0	1	1	0	0	44(2 π /70)
	1	0	1	0	0	0	0	45(2 π /70)
	1	0	1	0	0	0	1	46(2 π /70)
	1	0	1	0	0	1	0	47(2 π /70)
	1	0	1	0	0	1	1	48(2 π /70)
	1	0	1	0	1	0	0	49(2 π /70)
	1	0	1	1	0	0	0	50(2 π /70)
	1	0	1	1	0	0	1	51(2 π /70)
	1	0	1	1	0	1	0	52(2 π /70)
	1	0	1	1	0	1	1	53(2 π /70)
	1	0	1	1	1	0	0	54(2 π /70)
	1	1	0	0	0	0	0	55(2 π /70)
	1	1	0	0	0	0	1	56(2 π /70)
	1	1	0	0	0	1	0	57(2 π /70)
	1	1	0	0	0	1	1	58(2 π /70)
	1	1	0	0	1	0	0	59(2 π /70)
	1	1	0	1	0	0	0	60(2 π /70)
	1	1	0	1	0	0	1	61(2 π /70)
	1	1	0	1	0	1	0	62(2 π /70)
	1	1	0	1	0	1	1	63(2 π /70)
	1	1	0	1	1	0	0	64(2 π /70)
	1	1	1	0	0	0	0	65(2 π /70)
	1	1	1	0	0	0	1	66(2 π /70)
	1	1	1	0	0	1	0	67(2 π /70)
	1	1	1	0	0	1	1	68(2 π /70)
	1	1	1	0	1	0	0	69(2 π /70)

Divide Ratio	PHnADGC6	PHnADGC5	PHnADGC4	PHnADGC3	PHnADGC2	PHnADGC1	PHnADGC0	Phase Delay (radian)
n.12	n.11	n.10	n.9	n.8	n.7	n.6		
80	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	1	(2 π /80)
	0	0	0	0	0	1	0	2(2 π /80)
	0	0	0	0	0	1	1	3(2 π /80)
	0	0	0	0	1	0	0	4(2 π /80)
	0	0	0	1	0	0	0	5(2 π /80)
	0	0	0	1	0	0	1	6(2 π /80)
	0	0	0	1	0	1	0	7(2 π /80)
	0	0	0	1	0	1	1	8(2 π /80)
	0	0	0	1	1	0	0	9(2 π /80)
	0	0	1	0	0	0	0	10(2 π /80)
	0	0	1	0	0	0	1	11(2 π /80)
	0	0	1	0	0	1	0	12(2 π /80)
	0	0	1	0	0	1	1	13(2 π /80)
	0	0	1	0	1	0	0	14(2 π /80)
	0	0	1	1	0	0	0	15(2 π /80)
	0	0	1	1	0	0	1	16(2 π /80)
	0	0	1	1	0	1	0	17(2 π /80)
	0	0	1	1	0	1	1	18(2 π /80)
	0	0	1	1	1	0	0	19(2 π /80)
	0	1	0	0	0	0	0	20(2 π /80)
	0	1	0	0	0	0	1	21(2 π /80)
	0	1	0	0	0	1	0	22(2 π /80)
	0	1	0	0	0	1	1	23(2 π /80)
	0	1	0	0	1	0	0	24(2 π /80)
	0	1	0	1	0	0	0	25(2 π /80)
	0	1	0	1	0	0	1	26(2 π /80)
	0	1	0	1	0	1	0	27(2 π /80)
	0	1	0	1	0	1	1	28(2 π /80)
	0	1	0	1	1	0	0	29(2 π /80)
	0	1	1	0	0	0	0	30(2 π /80)
	0	1	1	0	0	0	1	31(2 π /80)
	0	1	1	0	0	1	0	32(2 π /80)
	0	1	1	0	0	1	1	33(2 π /80)
	0	1	1	0	1	0	0	34(2 π /80)
	0	1	1	1	0	0	0	35(2 π /80)
	0	1	1	1	0	0	1	36(2 π /80)
	0	1	1	1	0	1	0	37(2 π /80)
	0	1	1	1	0	1	1	38(2 π /80)
	0	1	1	1	1	0	0	39(2 π /80)
	1	0	0	0	0	0	0	40(2 π /80)
	1	0	0	0	0	0	1	41(2 π /80)
	1	0	0	0	0	1	0	42(2 π /80)
	1	0	0	0	0	1	1	43(2 π /80)
	1	0	0	0	1	0	0	44(2 π /80)
	1	0	0	1	0	0	0	45(2 π /80)
	1	0	0	1	0	0	1	46(2 π /80)
	1	0	0	1	0	1	0	47(2 π /80)
	1	0	0	1	0	1	1	48(2 π /80)
	1	0	0	1	1	0	0	49(2 π /80)
	1	0	1	0	0	0	0	50(2 π /80)
	1	0	1	0	0	0	1	51(2 π /80)
	1	0	1	0	0	1	0	52(2 π /80)
	1	0	1	0	0	1	1	53(2 π /80)
	1	0	1	0	1	0	0	54(2 π /80)
	1	0	1	1	0	0	0	55(2 π /80)
	1	0	1	1	0	0	1	56(2 π /80)
	1	0	1	1	0	1	0	57(2 π /80)
	1	0	1	1	0	1	1	58(2 π /80)
	1	0	1	1	1	0	0	59(2 π /80)
	1	1	0	0	0	0	0	60(2 π /80)
	1	1	0	0	0	0	1	61(2 π /80)
	1	1	0	0	0	1	0	62(2 π /80)
	1	1	0	0	0	1	1	63(2 π /80)
	1	1	0	0	1	0	0	64(2 π /80)
	1	1	0	1	0	0	0	65(2 π /80)
	1	1	0	1	0	0	1	66(2 π /80)
	1	1	0	1	0	1	0	67(2 π /80)
	1	1	0	1	0	1	1	68(2 π /80)
	1	1	0	1	1	0	0	69(2 π /80)
	1	1	1	0	0	0	0	70(2 π /80)
	1	1	1	0	0	0	1	71(2 π /80)
	1	1	1	0	0	1	0	72(2 π /80)
	1	1	1	0	0	1	1	73(2 π /80)
	1	1	1	0	1	0	0	74(2 π /80)
	1	1	1	1	0	0	0	75(2 π /80)
	1	1	1	1	0	0	1	76(2 π /80)
	1	1	1	1	0	1	0	77(2 π /80)
	1	1	1	1	0	1	1	78(2 π /80)
	1	1	1	1	1	0	0	79(2 π /80)

Auxiliary Output

Figure 27 shows the auxiliary output port. Table 26 lists how the auxiliary output port is controlled. The output buffer supports a maximum output frequency of 250 MHz and drives at LVCMOS levels. Refer to Table 19 for the list of divider settings that establishes the output frequency.

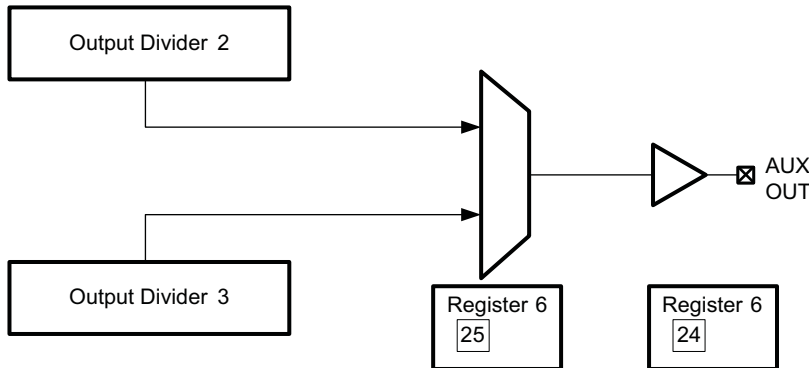


Figure 27. CDCE18005 Auxiliary Output

Table 26. CDCE18005 Auxiliary Output Settings

Bit Name → Register.Bit →	AUXFEEDSEL 6.25	AUXOUTEN 6.24	AUX OUTPUT SOURCE
	X	0	OFF
	0	1	Divider 2
	1	1	Divider 3

DEVICE POWER CALCULATION AND THERMAL MANAGEMENT

The CDCE18005 is a high performance device, therefore careful attention must be paid to device configuration and printed circuit board layout with respect to power consumption. Table 27 provides the power consumption for the individual blocks within the CDCE18005. To estimate total power consumption, calculate the sum of the products of the number of blocks used and the power dissipated of each corresponding block.

Provide Sample Calculation Here after numbers become available.

Table 27. CDCE18005 Power Consumption

Internal Block (Power at 3.3V)	Power Dissipated per Block (Typical)	Number of Blocks per Device
Input Circuit	18 mW	1
Output Divider	185 mW	5
Output Buffer (LVPECL)	116 mW	5
Output Buffer (LVDS)	76 mW	5
Output Buffer (LVCMOS)	86 mW	10

This power estimate determines the degree of thermal management required for a specific design. Employing the thermally enhanced printed circuit board layout shown in Figure 29 insures that the thermal performance curves shown in Figure 28 apply. Observing good thermal layout practices enables the thermal pad on the backside of the QFN-48 package to provide a good thermal path between the die contained within the package and the ambient air. This thermal pad also serves as the ground connection the device; therefore, a low inductance connection to the ground plane is essential.

Figure 29 shows a layout optimized for good thermal performance and a good power supply connection as well. The 7×7 filled via patter facilitates both considerations. Finally, the recommended layout achieves $\theta_{JA} = 27.3^{\circ}\text{C/W}$ in still air and 20.3°C/W in an environment with 100 LFM airflow if implemented on a JEDEC compliant thermal test board.

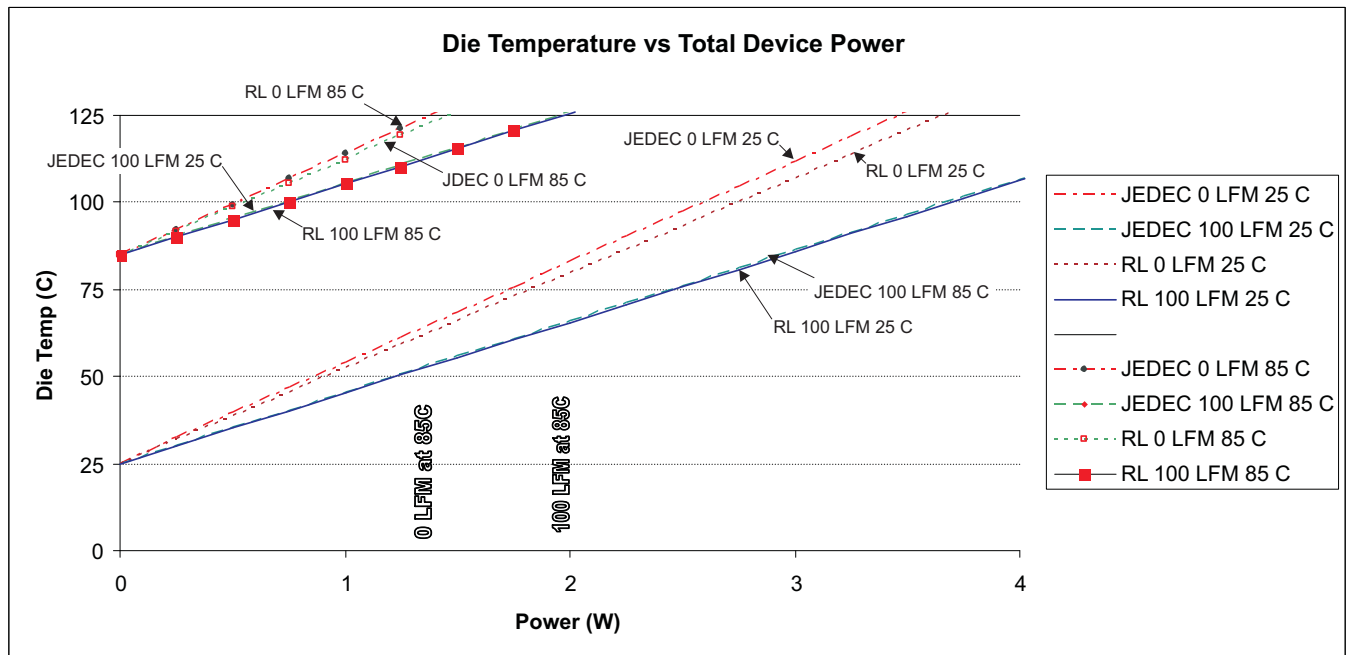


Figure 28. CDCE18005 Die Temperature vs Device Power

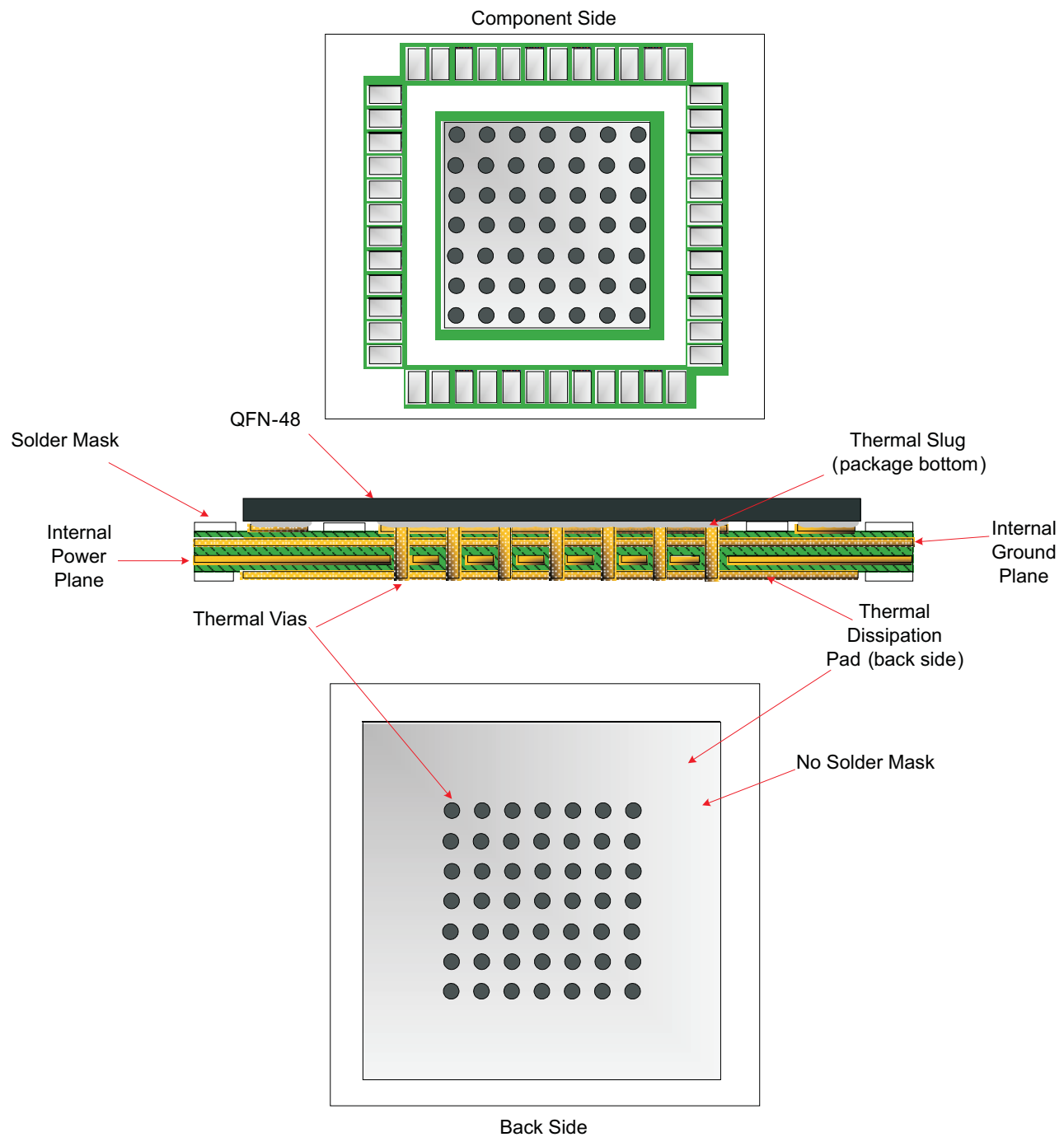


Figure 29. CDCE18005 Recommended PCB Layout

CDCE18005 Power Supply Bypassing – Recommended Layout

Figure 30 shows two conceptual layouts detailing recommended placement of power supply bypass capacitors. If the capacitors are mounted on the back side, 0402 components can be employed; however, soldering to the Thermal Dissipation Pad can be difficult. For component side mounting, use 0201 body size capacitors to facilitate signal routing. Keep the connections between the bypass capacitors and the power supply on the device as short as possible.

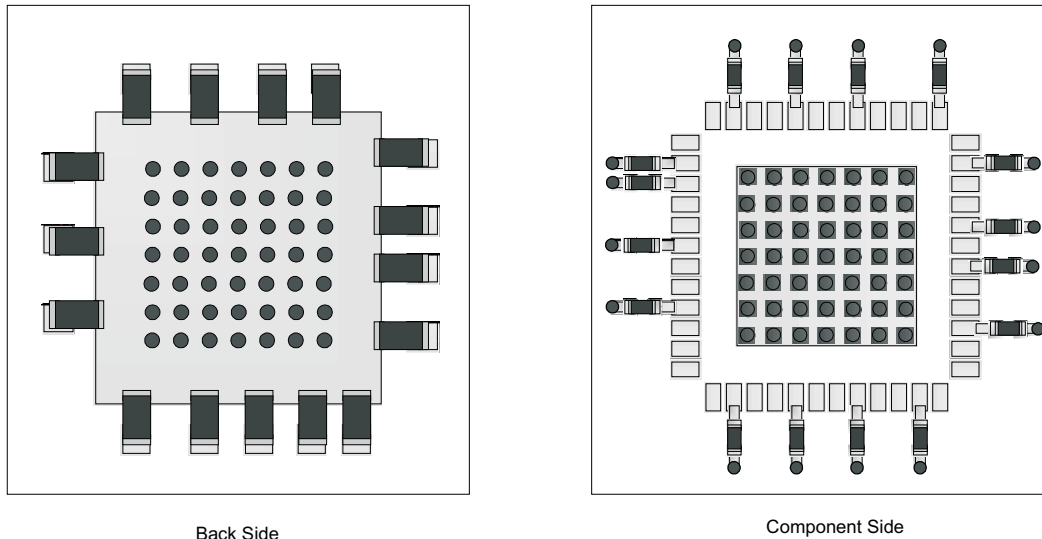


Figure 30. CDCE18005 Power Supply Bypassing

APPLICATION INFORMATION AND GENERAL USAGE HINTS

Fan-out Buffer

Each output of the CDCE18005 can be configured as a fan-out buffer (divider bypassed) or fan-out buffer with divide and skew control functionality.

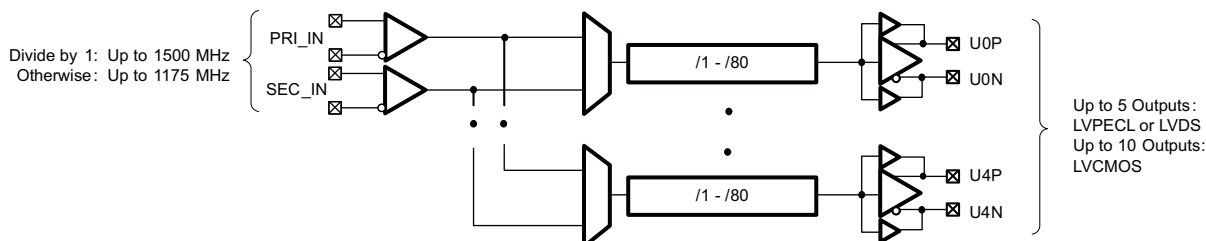


Figure 31. CDCE18005 Fan-out Buffer Mode

Clock Generator

The CDCE18005 can generate 5–10 low noise clocks from a single crystal or crystal oscillator as follows:

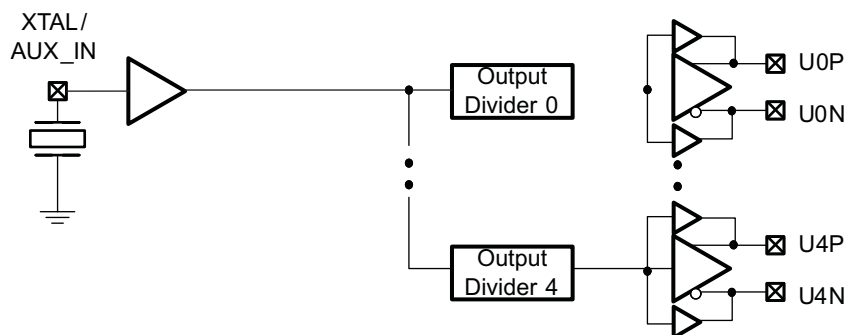


Figure 32. CDCE18005 Clock Generator Mode

Clock Distribution – Mixed Mode

The following table presents a common scenario where the CDCE18005 can function as a clock switch that accepts LVDS and crystal inputs and drives LVDS, LVPECL and LVCMOS outputs.

CLOCK FREQUENCY	INPUT/OUTPUT	FORMAT	NUMBER	CDCE18005 PORT	COMMENT
491.52 MHz	Input	LVDS	1	SEC_IN	Reference
125 MHz	Input	LVDS	1	PRI_IN	Reference from backplane
10 MHz	Input	AT-Cut	1	AUX_IN	Low end crystal oscillator
122.88 MHz	Output	LVDS	1	U0	SerDes Clock
491.52 MHz	Output	LVPECL	1	U1	ASIC
125 MHz	Output	LVPECL	1	U2	FPGA
30.72 MHz	Outputs	LVCMOS	2	U3	ASIC
10 MHz	Outputs	LVCMOS	2	U4	CPU, DSP

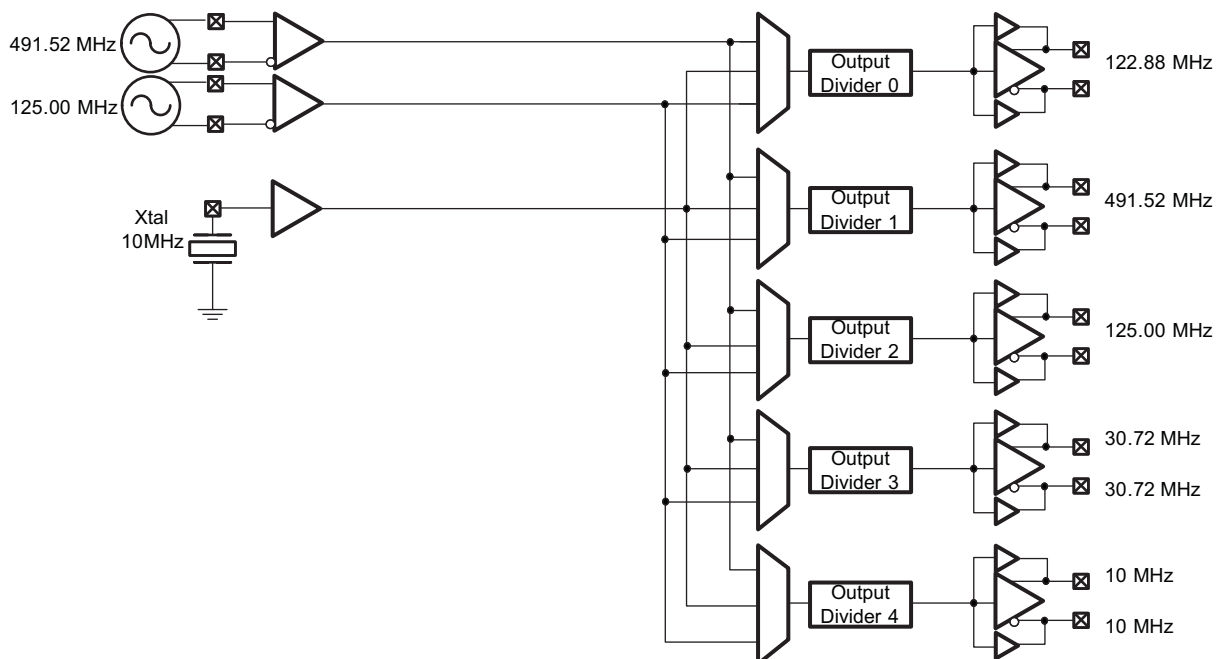


Figure 33. CDCE18005 Mixed Mode Clock Distribution Example

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CDCE18005RGZR	ACTIVE	VQFN	RGZ	48	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
CDCE18005RGZT	ACTIVE	VQFN	RGZ	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

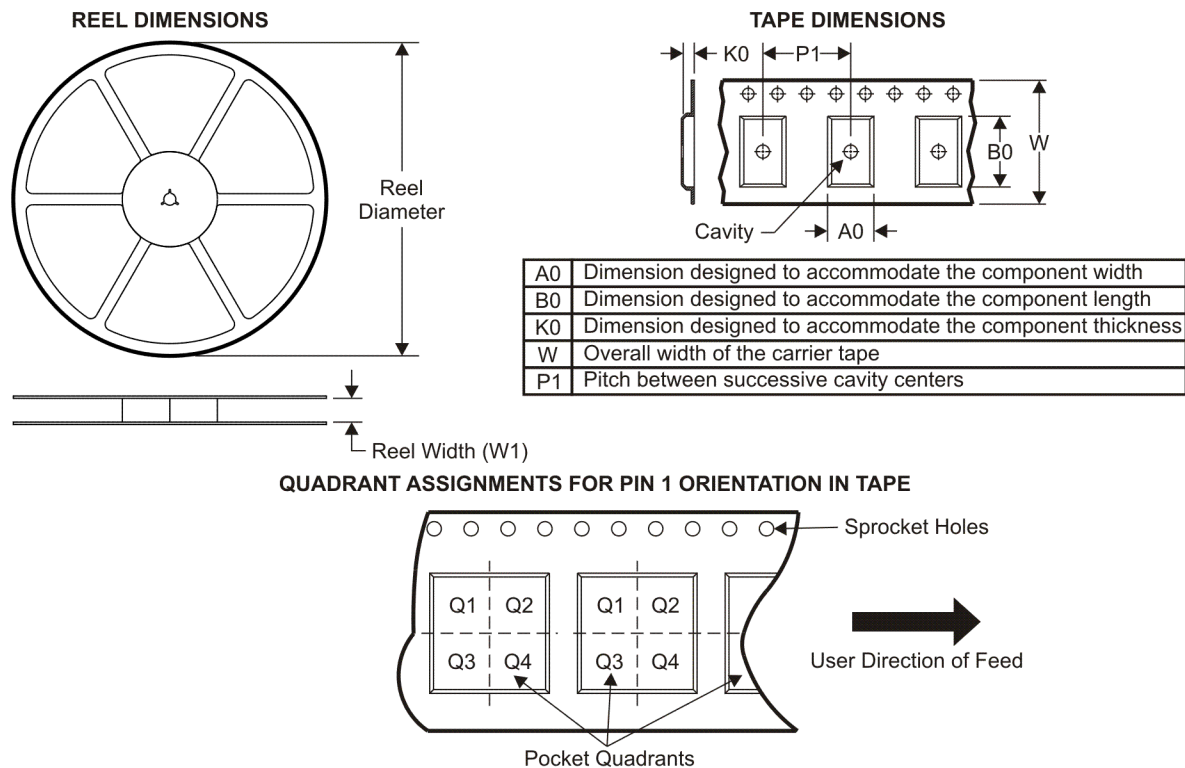
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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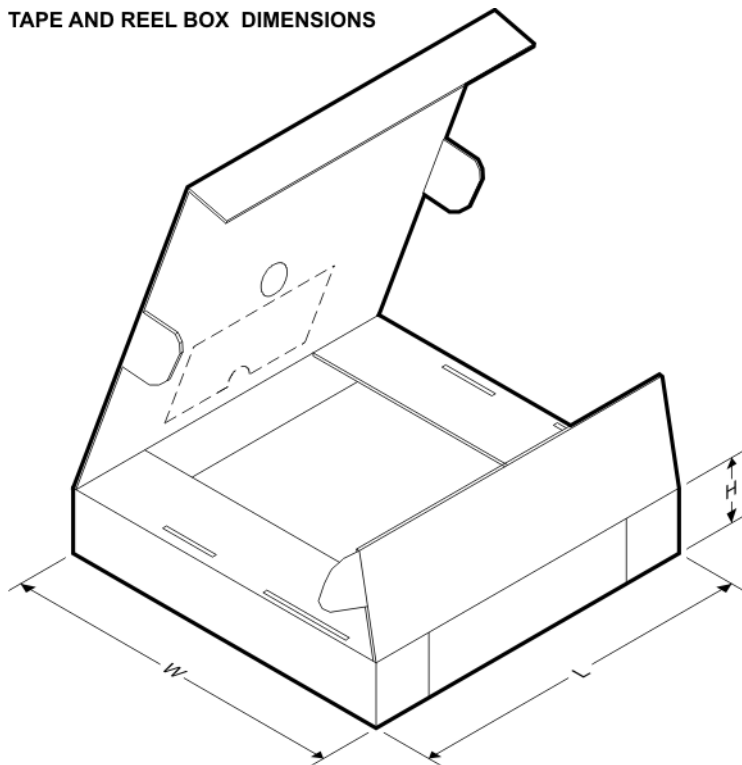
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCE18005RGZR	VQFN	RGZ	48	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
CDCE18005RGZT	VQFN	RGZ	48	250	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS

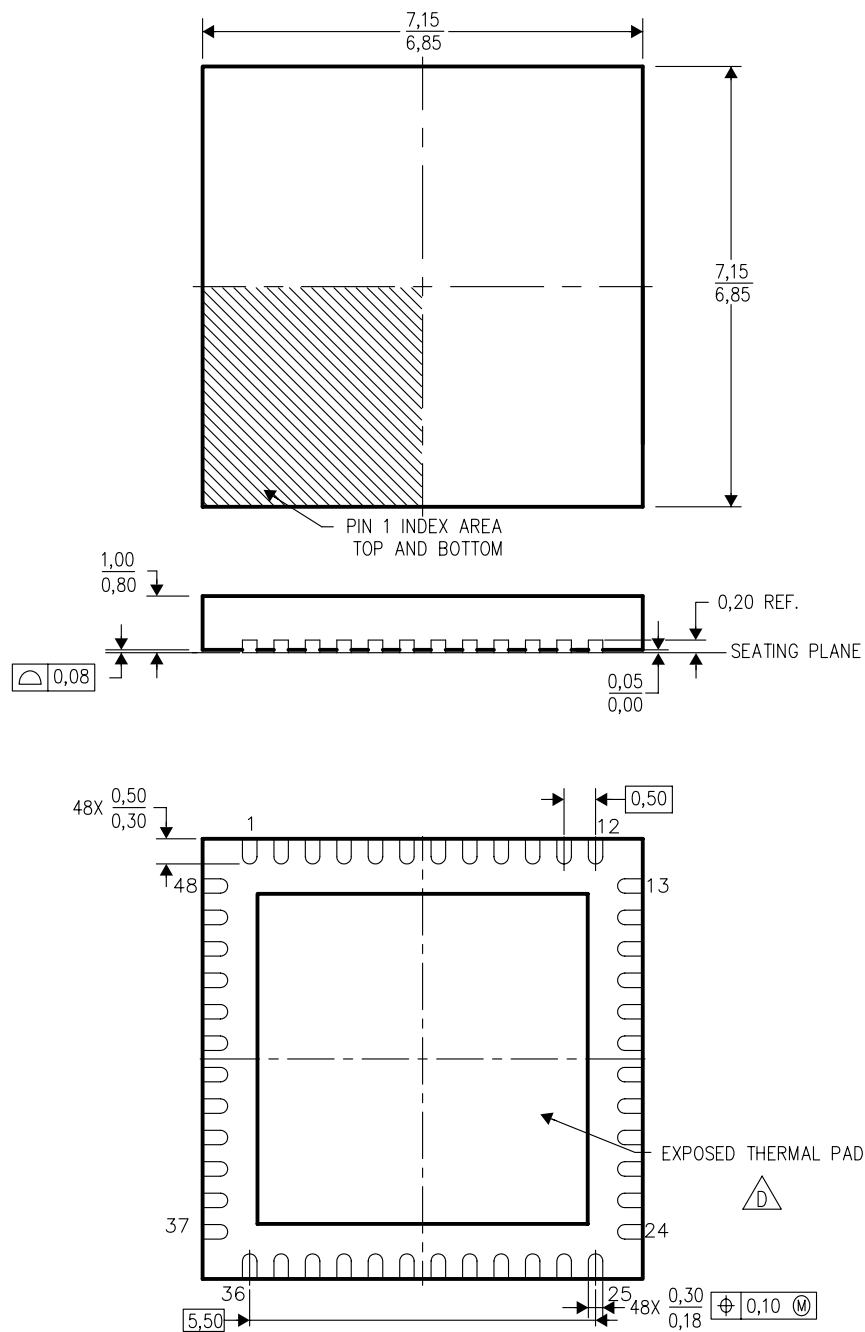


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCE18005RGZR	VQFN	RGZ	48	2500	333.2	345.9	28.6
CDCE18005RGZT	VQFN	RGZ	48	250	333.2	345.9	28.6

RGZ (S-PQFP-N48)

PLASTIC QUAD FLATPACK



4204101/E 11/04

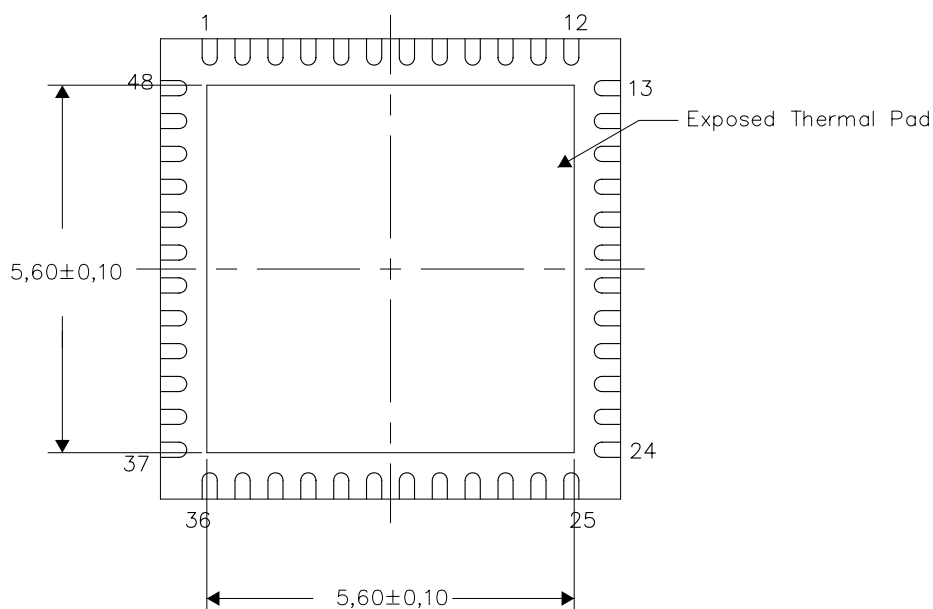
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
 - E. Falls within JEDEC MO-220.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



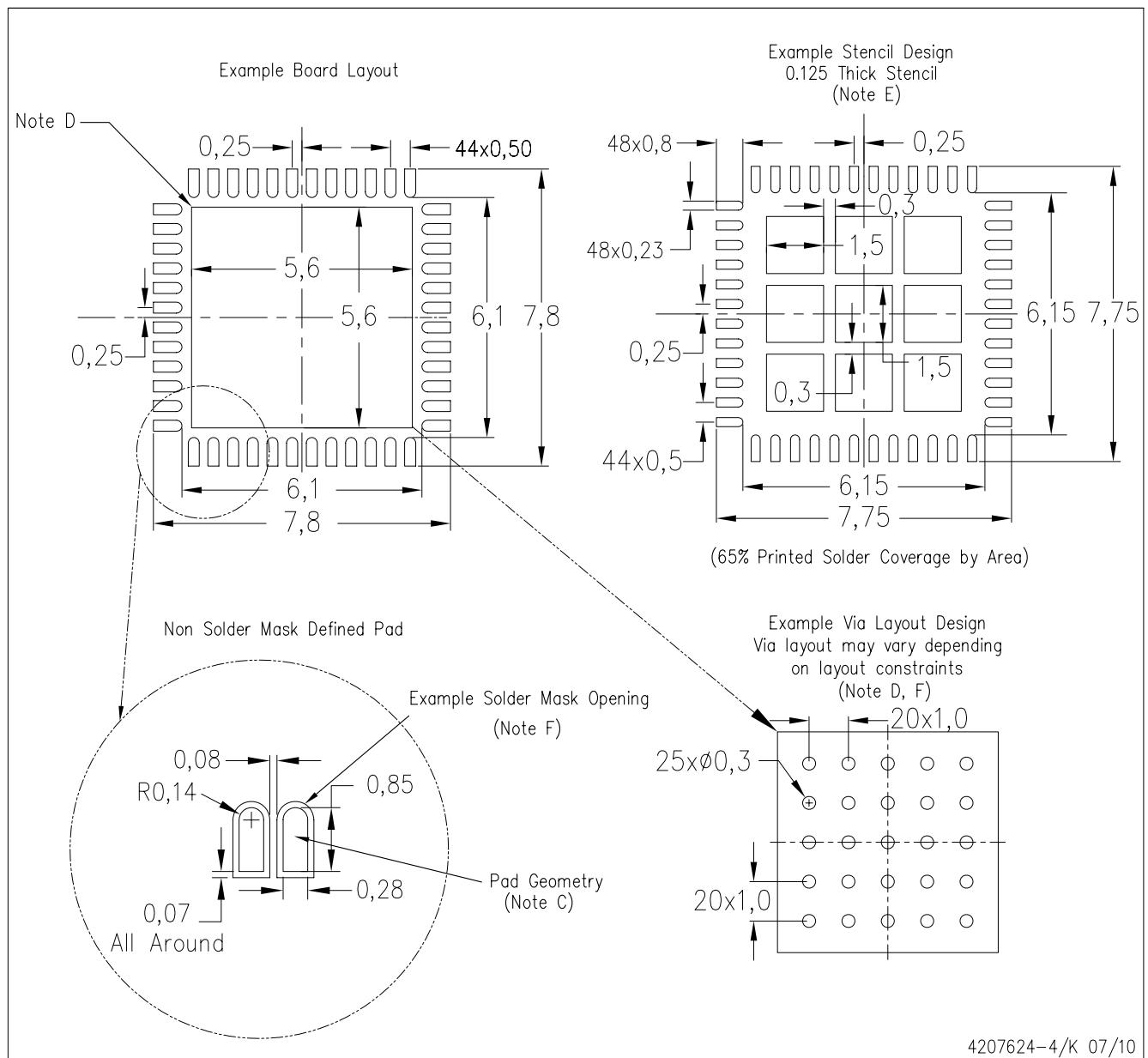
Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RGZ (S-PVQFN-N48)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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